

FOR AUTOMOTIVE 105°C OPERATION VOLTAGE DETECTOR WITH SENSE PIN

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Rev.1.2_01

The S-19103/19109 Series is a high-accuracy voltage detector developed using CMOS technology. The detection voltage is fixed internally with an accuracy of $\pm 3.5\%$ ($-V_{DET(S)} \geq 2.2 \text{ V}$). The release voltage is set to the same value as the detection voltage, since there is no hysteresis width. It operates with current consumption of 500 nA typ.

Apart from the power supply pin, the detection voltage input pin (SENSE pin) is also prepared, so the output is stable even if the SENSE pin falls to 0 V.

Two output forms Nch open-drain output and CMOS output are available.

Caution This product can be used in vehicle equipment and in-vehicle equipment. Before using the product in the purpose, contact to SII Semiconductor Corporation is indispensable.

■ Features

- Detection voltage: 1.0 V to 5.0 V (0.1 V step)
- Detection voltage accuracy: $\pm 3.5\%$ ($2.2 \text{ V} \leq -V_{DET(S)} \leq 5.0 \text{ V}$, $T_a = -40^\circ\text{C}$ to $+105^\circ\text{C}$)
 $\pm(2.5\% + 22 \text{ mV})$ ($1.0 \text{ V} \leq -V_{DET(S)} < 2.2 \text{ V}$, $T_a = -40^\circ\text{C}$ to $+105^\circ\text{C}$)
- Current consumption: 500 nA typ.
- Operation voltage range: 0.95 V to 10.0 V
- Output form: Nch open-drain output (Active "L")
 CMOS output (Active "L")
- Operation temperature range: $T_a = -40^\circ\text{C}$ to $+105^\circ\text{C}$
- Lead-free (Sn 100%), halogen-free
- AEC-Q100 qualified^{*1}

*1. Contact our sales office for details.

■ Applications

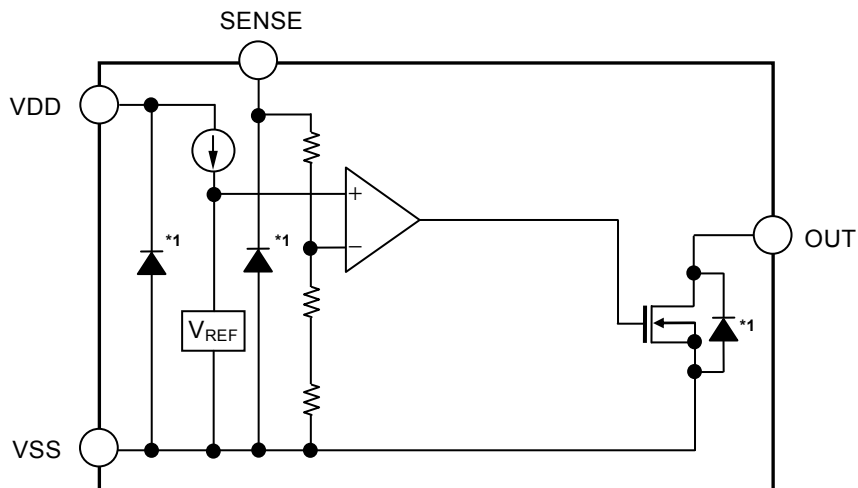
- For automotive use (accessory, car navigation system, car audio system, etc.)

■ Package

- SOT-23-5

■ Block Diagrams

1. S-19103/19109 Series N type (Nch open-drain output)

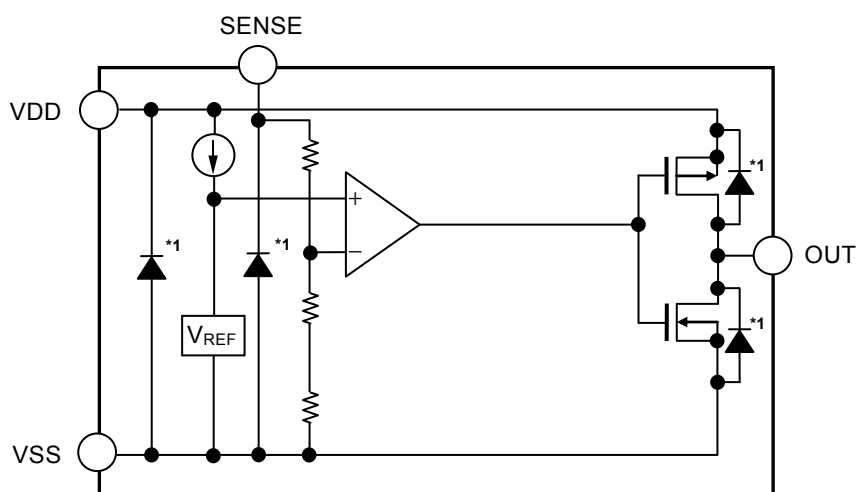


Function	Status
Output logic	Active "L"

*1. Parasitic diode

Figure 1

2. S-19103/19109 Series C type (CMOS output)



Function	Status
Output logic	Active "L"

*1. Parasitic diode

Figure 2

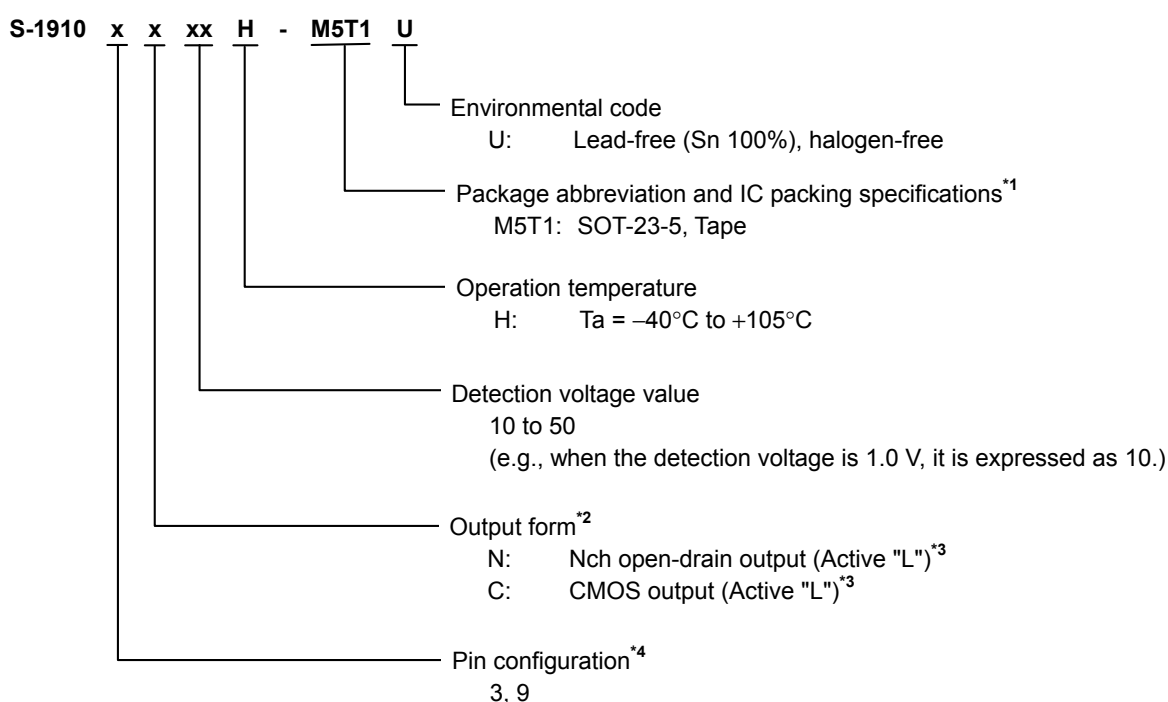
■ AEC-Q100 Qualified

This IC supports AEC-Q100 for operation temperature grade 2.
Contact our sales office for details of AEC-Q100 reliability specification.

■ Product Name Structure

Users can select the output form and detection voltage value for the S-19103/19109 Series.
Refer to "1. Product name" regarding the contents of product name, "2. Function list of product types" regarding the product types, "3. Package" regarding the package drawings and "4. Product name list" regarding details of product name.

1. Product name



*1. Refer to the tape drawing.

*2. Refer to "2. Function list of product types".

*3. If you request the product with output logic active "H", contact our sales office.

*4. Refer to "■ Pin Configurations".

2. Function list of product types

Table 1

Product Type	Output Form	Output Logic	Package
N	Nch open-drain output	Active "L"	SOT-23-5
C	CMOS output	Active "L"	SOT-23-5

3. Package

Table 2 Package Drawing Codes

Package Name	Dimension	Tape	Reel
SOT-23-5	MP005-A-P-SD	MP005-A-C-SD	MP005-A-R-SD

4. Product name list

4.1 S-19103 Series N type

Output form: Nch open-drain output (Active "L")

Table 3

Detection Voltage	SOT-23-5
1.0 V $\pm$ (2.5% + 22 mV)	S-19103N10H-M5T1U
1.1 V $\pm$ (2.5% + 22 mV)	S-19103N11H-M5T1U
1.2 V $\pm$ (2.5% + 22 mV)	S-19103N12H-M5T1U
1.3 V $\pm$ (2.5% + 22 mV)	S-19103N13H-M5T1U
1.4 V $\pm$ (2.5% + 22 mV)	S-19103N14H-M5T1U
1.5 V $\pm$ (2.5% + 22 mV)	S-19103N15H-M5T1U
1.6 V $\pm$ (2.5% + 22 mV)	S-19103N16H-M5T1U
1.7 V $\pm$ (2.5% + 22 mV)	S-19103N17H-M5T1U
1.8 V $\pm$ (2.5% + 22 mV)	S-19103N18H-M5T1U
1.9 V $\pm$ (2.5% + 22 mV)	S-19103N19H-M5T1U
2.0 V $\pm$ (2.5% + 22 mV)	S-19103N20H-M5T1U
2.1 V $\pm$ (2.5% + 22 mV)	S-19103N21H-M5T1U
2.2 V $\pm$ 3.5%	S-19103N22H-M5T1U
2.3 V $\pm$ 3.5%	S-19103N23H-M5T1U
2.4 V $\pm$ 3.5%	S-19103N24H-M5T1U
2.5 V $\pm$ 3.5%	S-19103N25H-M5T1U
2.6 V $\pm$ 3.5%	S-19103N26H-M5T1U
2.7 V $\pm$ 3.5%	S-19103N27H-M5T1U
2.8 V $\pm$ 3.5%	S-19103N28H-M5T1U
2.9 V $\pm$ 3.5%	S-19103N29H-M5T1U
3.0 V $\pm$ 3.5%	S-19103N30H-M5T1U
3.1 V $\pm$ 3.5%	S-19103N31H-M5T1U
3.2 V $\pm$ 3.5%	S-19103N32H-M5T1U
3.3 V $\pm$ 3.5%	S-19103N33H-M5T1U
3.4 V $\pm$ 3.5%	S-19103N34H-M5T1U
3.5 V $\pm$ 3.5%	S-19103N35H-M5T1U
3.6 V $\pm$ 3.5%	S-19103N36H-M5T1U
3.7 V $\pm$ 3.5%	S-19103N37H-M5T1U
3.8 V $\pm$ 3.5%	S-19103N38H-M5T1U
3.9 V $\pm$ 3.5%	S-19103N39H-M5T1U
4.0 V $\pm$ 3.5%	S-19103N40H-M5T1U
4.1 V $\pm$ 3.5%	S-19103N41H-M5T1U
4.2 V $\pm$ 3.5%	S-19103N42H-M5T1U
4.3 V $\pm$ 3.5%	S-19103N43H-M5T1U
4.4 V $\pm$ 3.5%	S-19103N44H-M5T1U
4.5 V $\pm$ 3.5%	S-19103N45H-M5T1U
4.6 V $\pm$ 3.5%	S-19103N46H-M5T1U
4.7 V $\pm$ 3.5%	S-19103N47H-M5T1U
4.8 V $\pm$ 3.5%	S-19103N48H-M5T1U
4.9 V $\pm$ 3.5%	S-19103N49H-M5T1U
5.0 V $\pm$ 3.5%	S-19103N50H-M5T1U

4.2 S-19103 Series C type

Output form: CMOS output (Active "L")

Table 4

Detection Voltage	SOT-23-5
1.0 V $\pm$ (2.5% + 22 mV)	S-19103C10H-M5T1U
1.1 V $\pm$ (2.5% + 22 mV)	S-19103C11H-M5T1U
1.2 V $\pm$ (2.5% + 22 mV)	S-19103C12H-M5T1U
1.3 V $\pm$ (2.5% + 22 mV)	S-19103C13H-M5T1U
1.4 V $\pm$ (2.5% + 22 mV)	S-19103C14H-M5T1U
1.5 V $\pm$ (2.5% + 22 mV)	S-19103C15H-M5T1U
1.6 V $\pm$ (2.5% + 22 mV)	S-19103C16H-M5T1U
1.7 V $\pm$ (2.5% + 22 mV)	S-19103C17H-M5T1U
1.8 V $\pm$ (2.5% + 22 mV)	S-19103C18H-M5T1U
1.9 V $\pm$ (2.5% + 22 mV)	S-19103C19H-M5T1U
2.0 V $\pm$ (2.5% + 22 mV)	S-19103C20H-M5T1U
2.1 V $\pm$ (2.5% + 22 mV)	S-19103C21H-M5T1U
2.2 V $\pm$ 3.5%	S-19103C22H-M5T1U
2.3 V $\pm$ 3.5%	S-19103C23H-M5T1U
2.4 V $\pm$ 3.5%	S-19103C24H-M5T1U
2.5 V $\pm$ 3.5%	S-19103C25H-M5T1U
2.6 V $\pm$ 3.5%	S-19103C26H-M5T1U
2.7 V $\pm$ 3.5%	S-19103C27H-M5T1U
2.8 V $\pm$ 3.5%	S-19103C28H-M5T1U
2.9 V $\pm$ 3.5%	S-19103C29H-M5T1U
3.0 V $\pm$ 3.5%	S-19103C30H-M5T1U
3.1 V $\pm$ 3.5%	S-19103C31H-M5T1U
3.2 V $\pm$ 3.5%	S-19103C32H-M5T1U
3.3 V $\pm$ 3.5%	S-19103C33H-M5T1U
3.4 V $\pm$ 3.5%	S-19103C34H-M5T1U
3.5 V $\pm$ 3.5%	S-19103C35H-M5T1U
3.6 V $\pm$ 3.5%	S-19103C36H-M5T1U
3.7 V $\pm$ 3.5%	S-19103C37H-M5T1U
3.8 V $\pm$ 3.5%	S-19103C38H-M5T1U
3.9 V $\pm$ 3.5%	S-19103C39H-M5T1U
4.0 V $\pm$ 3.5%	S-19103C40H-M5T1U
4.1 V $\pm$ 3.5%	S-19103C41H-M5T1U
4.2 V $\pm$ 3.5%	S-19103C42H-M5T1U
4.3 V $\pm$ 3.5%	S-19103C43H-M5T1U
4.4 V $\pm$ 3.5%	S-19103C44H-M5T1U
4.5 V $\pm$ 3.5%	S-19103C45H-M5T1U
4.6 V $\pm$ 3.5%	S-19103C46H-M5T1U
4.7 V $\pm$ 3.5%	S-19103C47H-M5T1U
4.8 V $\pm$ 3.5%	S-19103C48H-M5T1U
4.9 V $\pm$ 3.5%	S-19103C49H-M5T1U
5.0 V $\pm$ 3.5%	S-19103C50H-M5T1U

4.3 S-19109 Series N type

Output form: Nch open-drain output (Active "L")

Table 5

Detection Voltage	SOT-23-5
1.0 V $\pm$ (2.5% + 22 mV)	S-19109N10H-M5T1U
1.1 V $\pm$ (2.5% + 22 mV)	S-19109N11H-M5T1U
1.2 V $\pm$ (2.5% + 22 mV)	S-19109N12H-M5T1U
1.3 V $\pm$ (2.5% + 22 mV)	S-19109N13H-M5T1U
1.4 V $\pm$ (2.5% + 22 mV)	S-19109N14H-M5T1U
1.5 V $\pm$ (2.5% + 22 mV)	S-19109N15H-M5T1U
1.6 V $\pm$ (2.5% + 22 mV)	S-19109N16H-M5T1U
1.7 V $\pm$ (2.5% + 22 mV)	S-19109N17H-M5T1U
1.8 V $\pm$ (2.5% + 22 mV)	S-19109N18H-M5T1U
1.9 V $\pm$ (2.5% + 22 mV)	S-19109N19H-M5T1U
2.0 V $\pm$ (2.5% + 22 mV)	S-19109N20H-M5T1U
2.1 V $\pm$ (2.5% + 22 mV)	S-19109N21H-M5T1U
2.2 V $\pm$ 3.5%	S-19109N22H-M5T1U
2.3 V $\pm$ 3.5%	S-19109N23H-M5T1U
2.4 V $\pm$ 3.5%	S-19109N24H-M5T1U
2.5 V $\pm$ 3.5%	S-19109N25H-M5T1U
2.6 V $\pm$ 3.5%	S-19109N26H-M5T1U
2.7 V $\pm$ 3.5%	S-19109N27H-M5T1U
2.8 V $\pm$ 3.5%	S-19109N28H-M5T1U
2.9 V $\pm$ 3.5%	S-19109N29H-M5T1U
3.0 V $\pm$ 3.5%	S-19109N30H-M5T1U
3.1 V $\pm$ 3.5%	S-19109N31H-M5T1U
3.2 V $\pm$ 3.5%	S-19109N32H-M5T1U
3.3 V $\pm$ 3.5%	S-19109N33H-M5T1U
3.4 V $\pm$ 3.5%	S-19109N34H-M5T1U
3.5 V $\pm$ 3.5%	S-19109N35H-M5T1U
3.6 V $\pm$ 3.5%	S-19109N36H-M5T1U
3.7 V $\pm$ 3.5%	S-19109N37H-M5T1U
3.8 V $\pm$ 3.5%	S-19109N38H-M5T1U
3.9 V $\pm$ 3.5%	S-19109N39H-M5T1U
4.0 V $\pm$ 3.5%	S-19109N40H-M5T1U
4.1 V $\pm$ 3.5%	S-19109N41H-M5T1U
4.2 V $\pm$ 3.5%	S-19109N42H-M5T1U
4.3 V $\pm$ 3.5%	S-19109N43H-M5T1U
4.4 V $\pm$ 3.5%	S-19109N44H-M5T1U
4.5 V $\pm$ 3.5%	S-19109N45H-M5T1U
4.6 V $\pm$ 3.5%	S-19109N46H-M5T1U
4.7 V $\pm$ 3.5%	S-19109N47H-M5T1U
4.8 V $\pm$ 3.5%	S-19109N48H-M5T1U
4.9 V $\pm$ 3.5%	S-19109N49H-M5T1U
5.0 V $\pm$ 3.5%	S-19109N50H-M5T1U

4.4 S-19109 Series C type

Output form: CMOS output (Active "L")

Table 6

Detection Voltage	SOT-23-5
1.0 V $\pm$ (2.5% + 22 mV)	S-19109C10H-M5T1U
1.1 V $\pm$ (2.5% + 22 mV)	S-19109C11H-M5T1U
1.2 V $\pm$ (2.5% + 22 mV)	S-19109C12H-M5T1U
1.3 V $\pm$ (2.5% + 22 mV)	S-19109C13H-M5T1U
1.4 V $\pm$ (2.5% + 22 mV)	S-19109C14H-M5T1U
1.5 V $\pm$ (2.5% + 22 mV)	S-19109C15H-M5T1U
1.6 V $\pm$ (2.5% + 22 mV)	S-19109C16H-M5T1U
1.7 V $\pm$ (2.5% + 22 mV)	S-19109C17H-M5T1U
1.8 V $\pm$ (2.5% + 22 mV)	S-19109C18H-M5T1U
1.9 V $\pm$ (2.5% + 22 mV)	S-19109C19H-M5T1U
2.0 V $\pm$ (2.5% + 22 mV)	S-19109C20H-M5T1U
2.1 V $\pm$ (2.5% + 22 mV)	S-19109C21H-M5T1U
2.2 V $\pm$ 3.5%	S-19109C22H-M5T1U
2.3 V $\pm$ 3.5%	S-19109C23H-M5T1U
2.4 V $\pm$ 3.5%	S-19109C24H-M5T1U
2.5 V $\pm$ 3.5%	S-19109C25H-M5T1U
2.6 V $\pm$ 3.5%	S-19109C26H-M5T1U
2.7 V $\pm$ 3.5%	S-19109C27H-M5T1U
2.8 V $\pm$ 3.5%	S-19109C28H-M5T1U
2.9 V $\pm$ 3.5%	S-19109C29H-M5T1U
3.0 V $\pm$ 3.5%	S-19109C30H-M5T1U
3.1 V $\pm$ 3.5%	S-19109C31H-M5T1U
3.2 V $\pm$ 3.5%	S-19109C32H-M5T1U
3.3 V $\pm$ 3.5%	S-19109C33H-M5T1U
3.4 V $\pm$ 3.5%	S-19109C34H-M5T1U
3.5 V $\pm$ 3.5%	S-19109C35H-M5T1U
3.6 V $\pm$ 3.5%	S-19109C36H-M5T1U
3.7 V $\pm$ 3.5%	S-19109C37H-M5T1U
3.8 V $\pm$ 3.5%	S-19109C38H-M5T1U
3.9 V $\pm$ 3.5%	S-19109C39H-M5T1U
4.0 V $\pm$ 3.5%	S-19109C40H-M5T1U
4.1 V $\pm$ 3.5%	S-19109C41H-M5T1U
4.2 V $\pm$ 3.5%	S-19109C42H-M5T1U
4.3 V $\pm$ 3.5%	S-19109C43H-M5T1U
4.4 V $\pm$ 3.5%	S-19109C44H-M5T1U
4.5 V $\pm$ 3.5%	S-19109C45H-M5T1U
4.6 V $\pm$ 3.5%	S-19109C46H-M5T1U
4.7 V $\pm$ 3.5%	S-19109C47H-M5T1U
4.8 V $\pm$ 3.5%	S-19109C48H-M5T1U
4.9 V $\pm$ 3.5%	S-19109C49H-M5T1U
5.0 V $\pm$ 3.5%	S-19109C50H-M5T1U

■ Pin Configurations

1. S-19103 Series

1.1 SOT-23-5

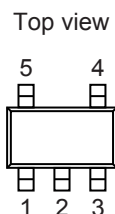


Figure 3

Table 7

Pin No.	Symbol	Description
1	OUT	Voltage detection output pin
2	VDD	Power supply pin
3	VSS	GND pin
4	NC ^{*1}	No connection
5	SENSE	Detection voltage input pin

*1. The NC pin is electrically open.
 The NC pin can be connected to the VDD pin or the VSS pin.

2. S-19109 Series

2.1 SOT-23-5

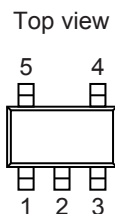


Figure 4

Table 8

Pin No.	Symbol	Description
1	OUT	Voltage detection output pin
2	VSS	GND pin
3	VDD	Power supply pin
4	SENSE	Detection voltage input pin
5	NC ^{*1}	No connection

*1. The NC pin is electrically open.
 The NC pin can be connected to the VDD pin or the VSS pin.

■ Absolute Maximum Ratings

Table 9

(Ta = -40°C to +105°C unless otherwise specified)

Item		Symbol	Absolute Maximum Rating	Unit
Power supply voltage		$V_{DD} - V_{SS}$	12.0	V
SENSE pin input voltage		V_{SENSE}	$V_{SS} - 0.3$ to 12.0	V
Output voltage	Nch open-drain output product	V_{OUT}	$V_{SS} - 0.3$ to 12.0	V
	CMOS output product		$V_{SS} - 0.3$ to $V_{DD} + 0.3$	V
Output current		I_{OUT}	50	mA
Operation ambient temperature		T_{opr}	-40 to +105	°C
Storage temperature		T_{stg}	-40 to +125	°C

Caution The absolute maximum ratings are rated values exceeding which the product could suffer physical damage. These values must therefore not be exceeded under any conditions.

■ Thermal Resistance Value

Table 10

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	
Junction-to-ambient thermal resistance*1	θ_{ja}	SOT-23-5	Board 1	—	192	—	°C/W
			Board 2	—	160	—	°C/W

*1. Test environment: compliance with JEDEC STANDARD JESD51-2A

Remark Refer to "■ Thermal Characteristics" for details of power dissipation and test board.

■ Electrical Characteristics

1. Nch open-drain output product

Table 11

(Ta = -40°C to +105°C unless otherwise specified)

Item	Symbol	Condition		Min.	Typ.	Max.	Unit	Test Circuit
Detection voltage*1	$-V_{DET}$	$0.95\text{ V} \leq V_{DD} \leq 10.0\text{ V}$	$1.0\text{ V} \leq -V_{DET(S)} < 2.2\text{ V}$	$-V_{DET(S)} \times 0.975 - 0.022$	$-V_{DET(S)}$	$-V_{DET(S)} \times 1.025 + 0.022$	V	1
			$2.2\text{ V} \leq -V_{DET(S)} \leq 5.0\text{ V}$	$-V_{DET(S)} \times 0.965$	$-V_{DET(S)}$	$-V_{DET(S)} \times 1.035$	V	1
Current consumption*2	I_{SS}	$V_{DD} = 10.0\text{ V}$, $V_{SENSE} = -V_{DET(S)} + 1.0\text{ V}$		—	0.50	0.90	μA	2
Operation voltage	V_{DD}	—		0.95	—	10.0	V	1
Output current	I_{OUT}	Output transistor Nch $V_{DS}^{*3} = 0.5\text{ V}$ $V_{SENSE} = 0.0\text{ V}$	$V_{DD} = 0.95\text{ V}$	0.50	1.00	—	mA	3
			$V_{DD} = 1.2\text{ V}$	0.73	1.33	—	mA	3
			$V_{DD} = 2.4\text{ V}$	1.17	2.39	—	mA	3
			$V_{DD} = 4.8\text{ V}$	1.49	2.50	—	mA	3
Leakage current	I_{LEAK}	Output transistor Nch $V_{DD} = 10.0\text{ V}$, $V_{DS}^{*3} = 10.0\text{ V}$, $V_{SENSE} = 10.0\text{ V}$		—	—	1.2	μA	3
Detection delay time*4	t_{DET}	$V_{DD} = 5.0\text{ V}$		—	40	—	μs	4
Release delay time*5	t_{RESET}	$V_{DD} = 5.0\text{ V}$	$-V_{DET(S)} \leq 2.4\text{ V}$	—	40	—	μs	4
			$2.4\text{ V} < -V_{DET(S)}$	—	80	—	μs	4
SENSE pin resistance	R_{SENSE}	$1.0\text{ V} \leq -V_{DET(S)} < 1.2\text{ V}$		4.0	19.0	72.0	MΩ	2
		$1.2\text{ V} \leq -V_{DET(S)} \leq 5.0\text{ V}$		4.8	30.0	189.0	MΩ	2

*1. $-V_{DET}$: Actual detection voltage value, $-V_{DET(S)}$: Set detection voltage value (the center value of the detection voltage range in **Table 3** or **Table 5**)

*2. The current flowing through the SENSE pin resistance is not included.

*3. V_{DS} : Drain-to-source voltage of the output transistor

*4. The time period from when the pulse voltage of $6.0\text{ V} \rightarrow -V_{DET(S)} - 2.0\text{ V}$ or 0 V is applied to the SENSE pin to when V_{OUT} reaches $V_{DD} / 2$, after the output pin is pulled up to 5.0 V by the resistance of $470\text{ k}\Omega$.

*5. The time period from when the pulse voltage of $0\text{ V} \rightarrow -V_{DET(S)} + 2.0\text{ V}$ or 6.0 V is applied to the SENSE pin to when V_{OUT} reaches $V_{DD} / 2$, after the output pin is pulled up to 5.0 V by the resistance of $470\text{ k}\Omega$.

2. CMOS output product

Table 12

(Ta = -40°C to +105°C unless otherwise specified)

Item	Symbol	Condition		Min.	Typ.	Max.	Unit	Test Circuit
Detection voltage*1	$-V_{DET}$	$0.95\text{ V} \leq V_{DD} \leq 10.0\text{ V}$	$1.0\text{ V} \leq -V_{DET(S)} < 2.2\text{ V}$	$-V_{DET(S)} \times 0.975 - 0.022$	$-V_{DET(S)}$	$-V_{DET(S)} \times 1.025 + 0.022$	V	1
			$2.2\text{ V} \leq -V_{DET(S)} \leq 5.0\text{ V}$	$-V_{DET(S)} \times 0.965$	$-V_{DET(S)}$	$-V_{DET(S)} \times 1.035$	V	1
Current consumption*2	I_{SS}	$V_{DD} = 10.0\text{ V}$, $V_{SENSE} = -V_{DET(S)} + 1.0\text{ V}$		—	0.50	2.10	μA	2
Operation voltage	V_{DD}	—		0.95	—	10.0	V	1
Output current	I_{OUT}	Output transistor Nch $V_{DS}^{*3} = 0.5\text{ V}$ $V_{SENSE} = 0.0\text{ V}$	$V_{DD} = 0.95\text{ V}$	0.50	1.00	—	mA	3
			$V_{DD} = 1.2\text{ V}$	0.73	1.33	—	mA	3
			$V_{DD} = 2.4\text{ V}$	1.17	2.39	—	mA	3
			$V_{DD} = 4.8\text{ V}$	1.49	2.50	—	mA	3
		Output transistor Pch $V_{DS}^{*3} = 0.5\text{ V}$ $V_{SENSE} = 10.0\text{ V}$	$V_{DD} = 4.8\text{ V}$	1.62	2.60	—	mA	5
			$V_{DD} = 6.0\text{ V}$	1.78	2.86	—	mA	5
Detection delay time*4	t_{DET}	$V_{DD} = 5.0\text{ V}$		—	40	—	μs	4
Release delay time*5	t_{RESET}	$V_{DD} = 5.0\text{ V}$	$-V_{DET(S)} \leq 2.4\text{ V}$	—	40	—	μs	4
			$2.4\text{ V} < -V_{DET(S)}$	—	80	—	μs	4
SENSE pin resistance	R_{SENSE}	$1.0\text{ V} \leq -V_{DET(S)} < 1.2\text{ V}$		4.0	19.0	72.0	MΩ	2
		$1.2\text{ V} \leq -V_{DET(S)} \leq 5.0\text{ V}$		4.8	30.0	189.0	MΩ	2

*1. $-V_{DET}$: Actual detection voltage value, $-V_{DET(S)}$: Set detection voltage value (the center value of the detection voltage range in **Table 4** or **Table 6**)

*2. The current flowing through the SENSE pin resistance is not included.

*3. V_{DS} : Drain-to-source voltage of the output transistor

*4. The time period from when the pulse voltage of $6.0\text{ V} \rightarrow -V_{DET(S)} - 2.0\text{ V}$ or 0 V is applied to the SENSE pin to when V_{OUT} reaches $V_{DD} / 2$.

*5. The time period from when the pulse voltage of $0\text{ V} \rightarrow -V_{DET(S)} + 2.0\text{ V}$ or 6.0 V is applied to the SENSE pin to when V_{OUT} reaches $V_{DD} / 2$.

■ Test Circuits

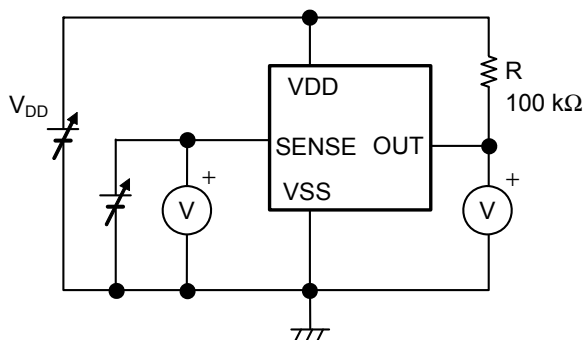


Figure 5 Test Circuit 1
(Nch open-drain output product)

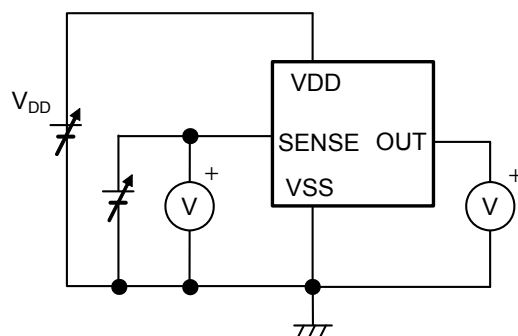


Figure 6 Test Circuit 1
(CMOS output product)

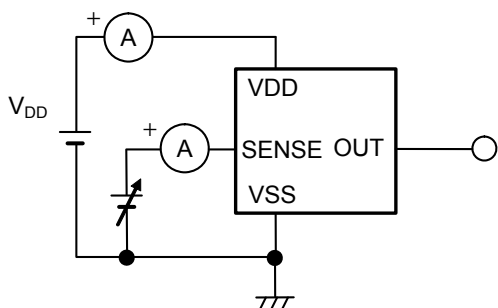


Figure 7 Test Circuit 2

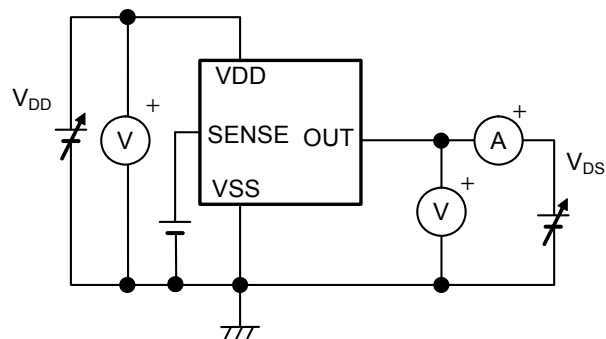


Figure 8 Test Circuit 3

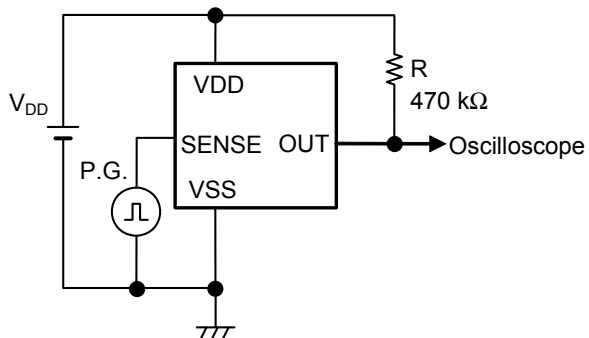


Figure 9 Test Circuit 4
(Nch open-drain output product)

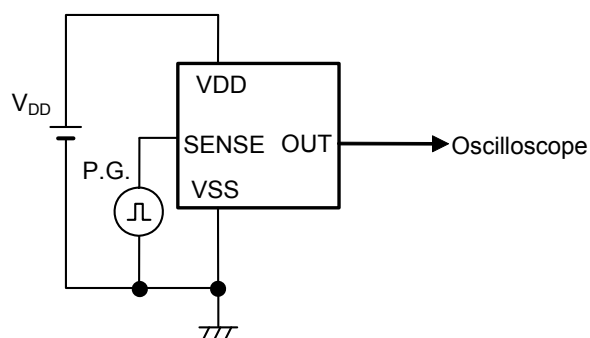


Figure 10 Test Circuit 4
(CMOS output product)

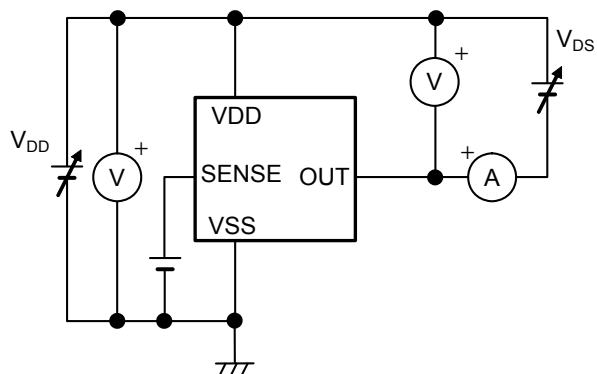


Figure 11 Test Circuit 5

■ Standard Circuits

1. Nch open-drain output product

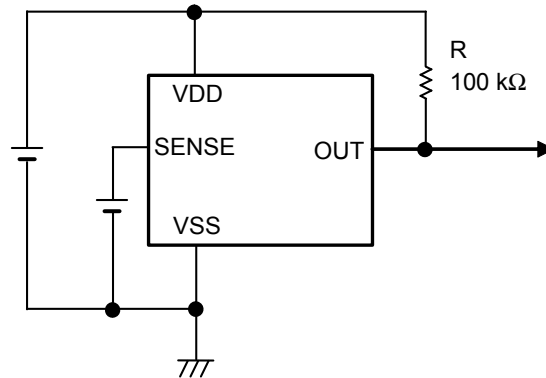


Figure 12

2. CMOS output product

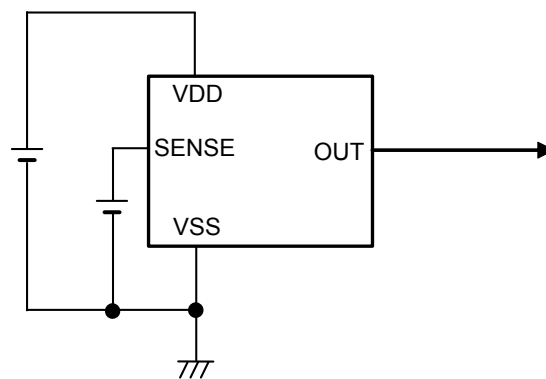


Figure 13

Caution The above connection diagram and constant will not guarantee successful operation. Perform thorough evaluation using the actual application to set the constant.

■ Explanation of Terms

1. Detection voltage ($-V_{DET}$)

The detection voltage is a voltage at which the output in **Figure 16** or **Figure 17** turns to "L". The detection voltage varies slightly among products of the same specification. The variation of detection voltage between the specified minimum ($-V_{DET}$ min.) and the maximum ($-V_{DET}$ max.) is called the detection voltage range (Refer to **Figure 14**).

Example: In the S-19103C18, the detection voltage is either one in the range of $1.733\text{ V} \leq -V_{DET} \leq 1.867\text{ V}$.
This means that some S-19103C18 have $-V_{DET} = 1.733\text{ V}$ and some have $-V_{DET} = 1.867\text{ V}$.

2. Release voltage ($+V_{DET}$)

The release voltage is a voltage at which the output in **Figure 16** or **Figure 17** turns to "H". The release voltage varies slightly among products of the same specification. The variation of release voltage between the specified minimum ($+V_{DET}$ min.) and the maximum ($+V_{DET}$ max.) is called the release voltage range (Refer to **Figure 15**). The release voltage ($+V_{DET}$) is the same value as the actual detection voltage ($-V_{DET}$) of a product.

Example: For the S-19103C18, the release voltage is either one in the range of $1.733\text{ V} \leq +V_{DET} \leq 1.867\text{ V}$.
This means that some S-19103C18 have $+V_{DET} = 1.733\text{ V}$ and some have $+V_{DET} = 1.867\text{ V}$.

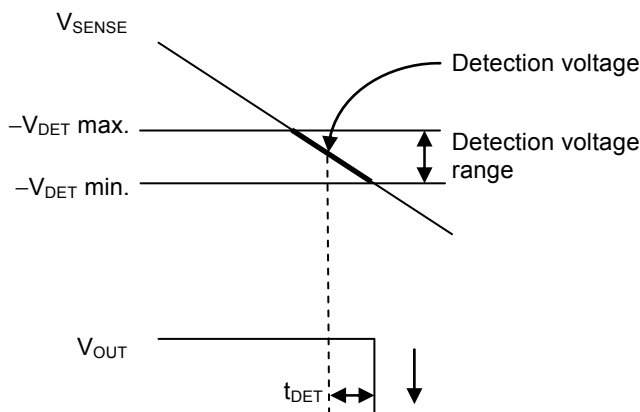


Figure 14 Detection Voltage

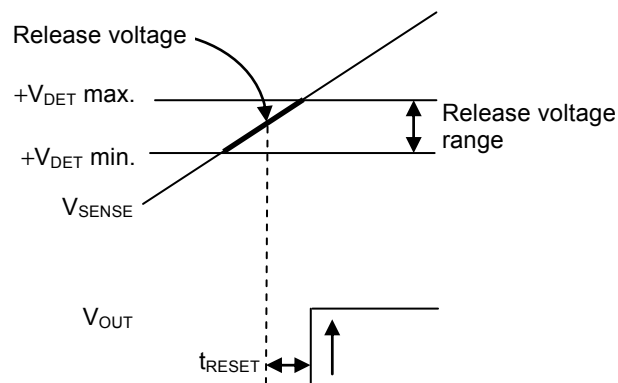


Figure 15 Release Voltage

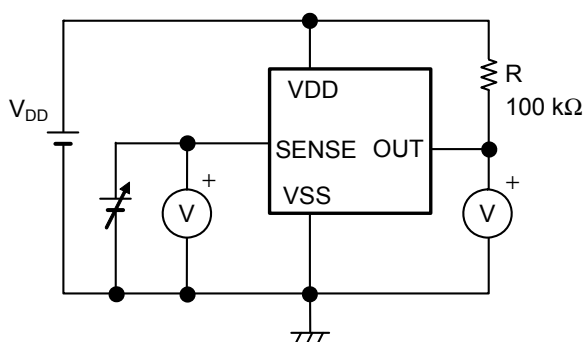


Figure 16 Test Circuit of Detection Voltage and Release Voltage
(Nch open-drain output product)

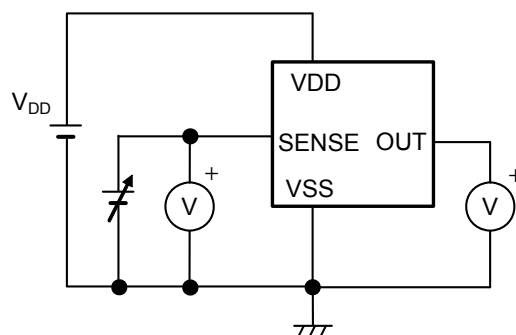


Figure 17 Test Circuit of Detection Voltage and Release Voltage
(CMOS output product)

3. Feed-through current

The feed-through current is a current that flows instantaneously to the VDD pin at the time of detection and release of a voltage detector. The feed-through current is large in CMOS output product, small in Nch open-drain output product.

4. Oscillation

In applications where an input resistor is connected (**Figure 18**), taking a CMOS output (active "L") product for example, the feed-through current which is generated when the output goes from "L" to "H" (at the time of release) causes a voltage drop equal to [feed-through current] $\times$ [input resistance]. Since the VDD pin and the SENSE pin are shorted as in **Figure 18**, the SENSE pin voltage drops at the time of release. Then the SENSE pin voltage drops below the detection voltage and the output goes from "H" to "L". In this status, the feed-through current stops and its resultant voltage drop disappears, and the output goes from "L" to "H". The feed-through current is then generated again, a voltage drop appears, and repeating the process finally induces oscillation.

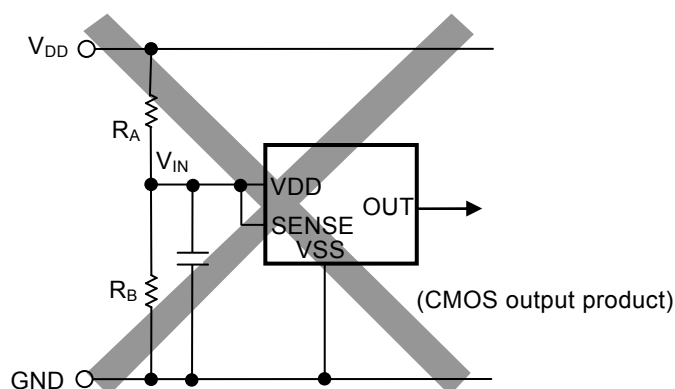


Figure 18 Example for Bad Implementation Due to Detection Voltage Change

Caution The release voltage is set to the same value as the detection voltage, since there is no hysteresis width in the S-19103/19109 Series. Therefore, the output goes from "H" to "L" if the power supply voltage (V_{DD}) reaches the detection voltage. The voltage which once became to "L" goes from "L" to "H" again. This repeating process may induce oscillation as well. Perform thorough evaluation using the actual application.

■ Operation

1. Basic operation

1.1 S-19103/19109 Series N type

- (1) When the power supply voltage (V_{DD}) is the minimum operation voltage or higher, and the SENSE pin voltage (V_{SENSE}) is the release voltage ($+V_{DET}$) or higher, the Nch transistor is turned off to output V_{DD} ("H") when the output is pulled up.

At this time, the input voltage to the comparator is $\frac{(R_B + R_C) \cdot V_{SENSE}}{R_A + R_B + R_C}$.

- (2) When V_{SENSE} decreases to $-V_{DET}$ or lower (point A in **Figure 20**), the Nch transistor is turned on. And then V_{SS} ("L") is output from the OUT pin after the elapse of the detection delay time (t_{DET}).
- (3) Even if V_{SENSE} further decreases to the IC's minimum operation voltage or lower, the output from the OUT pin is stable when V_{DD} is minimum operation voltage or higher.
- (4) Even if V_{SENSE} increases, V_{SS} is output when V_{SENSE} is lower than $+V_{DET}$.
- (5) When V_{SENSE} increases to $+V_{DET}$ or higher (point B in **Figure 20**), the Nch transistor is turned off. And then V_{DD} is output from the OUT pin after the elapse of the release delay time (t_{RESET}) when the output is pulled up.

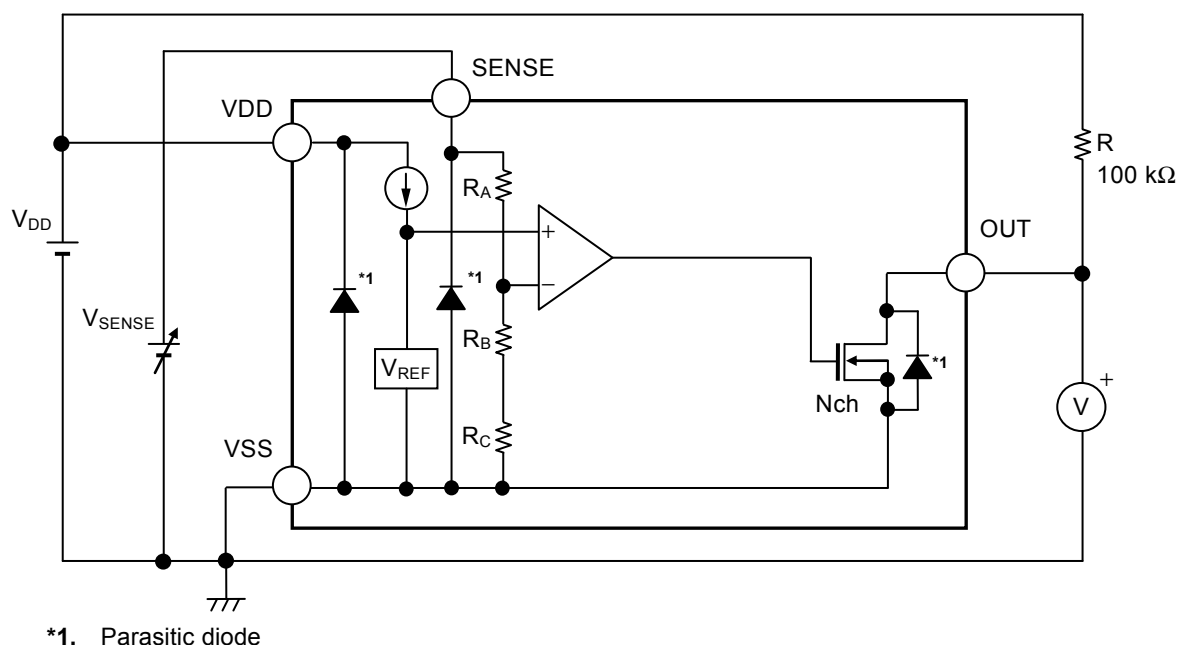
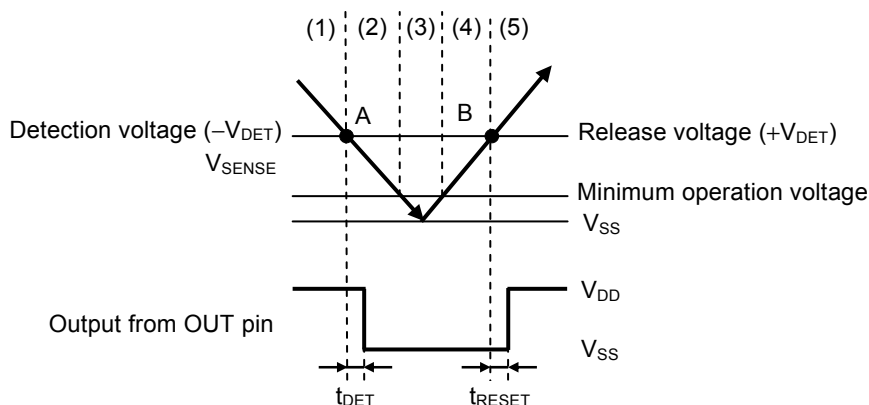


Figure 19 Operation of S-19103/19109 Series N Type



Remark The release voltage is set to the same value as the detection voltage, since there is no hysteresis width.

Figure 20 Timing Chart of S-19103/19109 Series N Type

1.2 S-19103/19109 Series C type

- (1) When the power supply voltage (V_{DD}) is the minimum operation voltage or higher, and the SENSE pin voltage (V_{SENSE}) is the release voltage ($+V_{DET}$) or higher, the Nch transistor is turned off and the Pch transistor is turned on to output V_{DD} ("H").

At this time, the input voltage to the comparator is $\frac{(R_B + R_C) \cdot V_{SENSE}}{R_A + R_B + R_C}$.

- (2) When V_{SENSE} decreases to $-V_{DET}$ or lower (point A in **Figure 22**), the Nch transistor is turned on and the Pch transistor is turned off. And then V_{SS} ("L") is output from the OUT pin after the elapse of the detection delay time (t_{DET}).
- (3) Even if V_{SENSE} further decreases to the IC's minimum operation voltage or lower, the output from the OUT pin is stable when V_{DD} is minimum operation voltage or higher.
- (4) Even if V_{SENSE} increases, V_{SS} is output when V_{SENSE} is lower than $+V_{DET}$.
- (5) When V_{SENSE} increases to $+V_{DET}$ or higher (point B in **Figure 22**), the Nch transistor is turned off and the Pch transistor is turned on. And then V_{DD} is output from the OUT pin after the elapse of the release delay time (t_{RESET}).

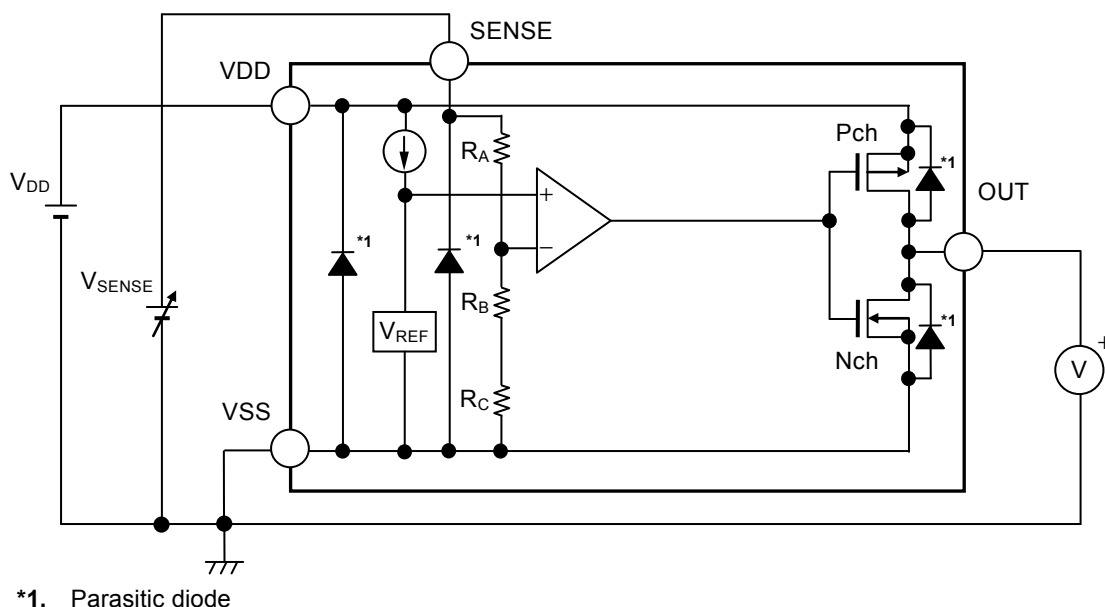
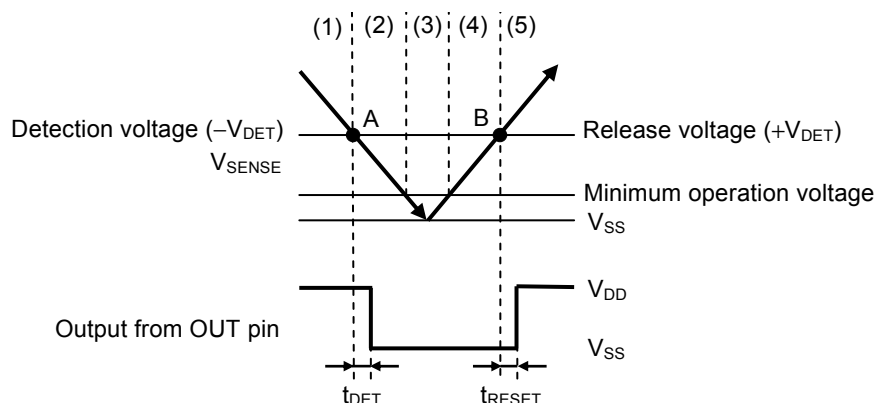


Figure 21 Operation of S-19103/19109 Series C Type



Remark The release voltage is set to the same value as the detection voltage, since there is no hysteresis width.

Figure 22 Timing Chart of S-19103/19109 Series C Type

2. SENSE pin

2.1 Error when detection voltage is set externally

By connecting a node that was resistance-divided by the resistor (R_A) and the resistor (R_B) to the SENSE pin as seen in **Figure 23**, the detection voltage can be set externally.

For conventional products without the SENSE pin, R_A cannot be too large since the resistance-divided node must be connected to the VDD pin. This is because a feed-through current will flow through the VDD pin when it goes from detection to release, and if R_A is large, problems such as oscillation may occur.

In the S-19103/19109 Series, R_A and R_B are easily made larger since the resistance-divided node can be connected to the SENSE pin through which no feed-through current flows. However, be careful of error in the current flowing through the internal resistance (R_{SENSE}) that will occur.

Although R_{SENSE} in the S-19103/19109 Series is large (4 M Ω min.) to make the error small, R_A and R_B should be selected such that the error is within the allowable limits.

2.2 Selection of R_A and R_B

In **Figure 23**, the relation between the external setting detection voltage (V_{DX}) and the actual detection voltage ($-V_{DET}$) is ideally calculated by the equation below.

$$V_{DX} = -V_{DET} \times \left(1 + \frac{R_A}{R_B}\right) \quad \cdots (1)$$

However, in reality there is an error in the current flowing through R_{SENSE} .

When considering this error, the relation between V_{DX} and $-V_{DET}$ is calculated as follows.

$$\begin{aligned} V_{DX} &= -V_{DET} \times \left(1 + \frac{R_A}{R_B \parallel R_{SENSE}}\right) \\ &= -V_{DET} \times \left(1 + \frac{R_A}{\frac{R_B \times R_{SENSE}}{R_B + R_{SENSE}}}\right) \\ &= -V_{DET} \times \left(1 + \frac{R_A}{R_B}\right) + \frac{R_A}{R_{SENSE}} \times -V_{DET} \quad \cdots (2) \end{aligned}$$

By using equations (1) and (2), the error is calculated as $-V_{DET} \times \frac{R_A}{R_{SENSE}}$.

The error rate is calculated as follows by dividing the error by the right-hand side of equation (1).

$$\frac{R_A \times R_B}{R_{SENSE} \times (R_A + R_B)} \times 100 [\%] = \frac{R_A \parallel R_B}{R_{SENSE}} \times 100 [\%] \quad \cdots (3)$$

As seen in equation (3), the smaller the resistance values of R_A and R_B compared to R_{SENSE} , the smaller the error rate becomes.

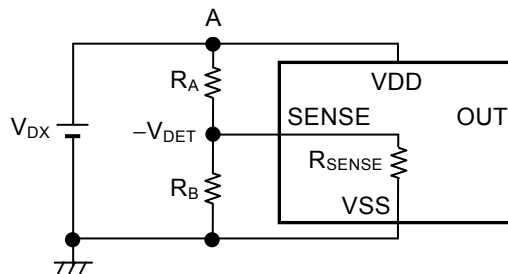


Figure 23 Detection Voltage External Setting Circuit

- Caution 1.** If parasitic resistance and parasitic inductance between V_{DX} and point A and between point A and VDD pin are large, oscillation may occur. Perform thorough evaluation using the actual application.
- 2.** If R_A and R_B are large, the SENSE pin input impedance becomes higher and may cause a malfunction due to noise. In this case, connect a capacitor between the SENSE pin and the VSS pin.

2.3 Power on sequence

Apply power in the order, the VDD pin then the SENSE pin.

As seen in **Figure 24**, when $V_{\text{SENSE}} \geq +V_{\text{DET}}$, the OUT pin output (V_{OUT}) rises and the S-19103/19109 Series becomes the release status (normal operation).

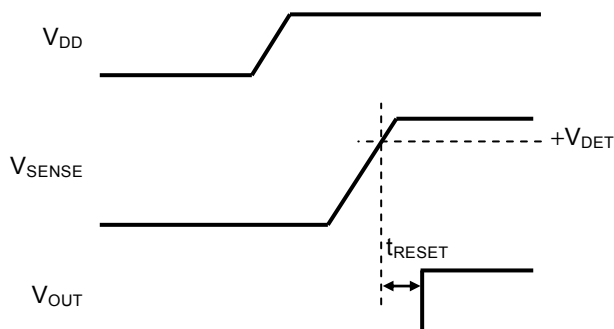


Figure 24

Caution If power is applied in the order the SENSE pin then the VDD pin, an erroneous release may occur even if $V_{\text{SENSE}} < +V_{\text{DET}}$.

2.4 Precautions when shorting between the VDD pin and the SENSE pin

2.4.1 Input resistor

Do not connect the input resistor (R_A) when shorting between the VDD pin and the SENSE pin.

A feed-through current flows through the VDD pin at the time of release. When connecting the circuit shown as **Figure 25**, the feed-through current of the VDD pin flowing through R_A will cause a drop in V_{SENSE} at the time of release.

At that time, oscillation may occur if $V_{\text{SENSE}} \leq -V_{\text{DET}}$.

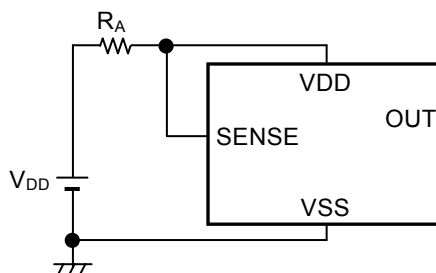


Figure 25

2.4.2 Parasitic resistance and parasitic capacitance

Due to the difference in parasitic resistance and parasitic capacitance of the VDD pin and the SENSE pin, power may be applied to the SENSE pin first.

Note that an erroneous release may occur if this happens (refer to "2.3 Power on sequence").

Caution In CMOS output product, make sure that the VDD pin input impedance does not become too high, regardless of the above. Since a feed-through current is large, a malfunction may occur if the VDD pin voltage changes greatly at the time of release.

2.5 Malfunction when V_{DD} falls

As seen in **Figure 26**, note that if the V_{DD} pin voltage (V_{DD}) drops steeply below 1.2 V when $-V_{DET} < V_{SENSE} < -V_{DET} \times 1.05$, erroneous detection may occur.

When $V_{DD_Low} \geq 1.2$ V, erroneous detection does not occur.

When $V_{DD_Low} < 1.2$ V, the more the V_{DD} falling amplitude increases or the shorter the falling time becomes, the easier the erroneous detection.

Perform thorough evaluation in actual application.

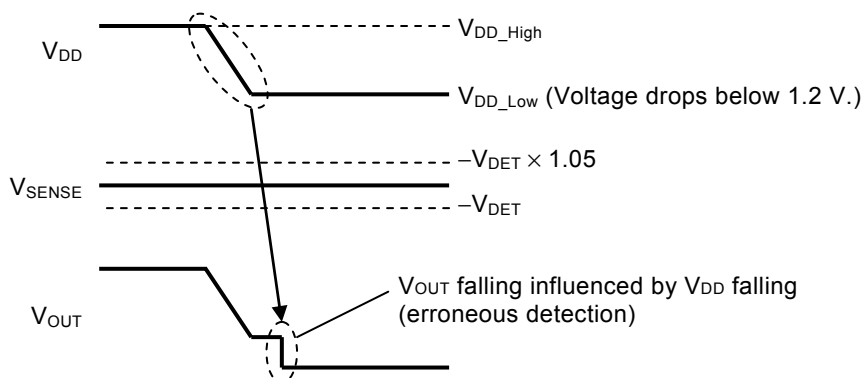


Figure 26

The S-19103C50 example in **Figure 27** shows an example of erroneous detection boundary conditions.

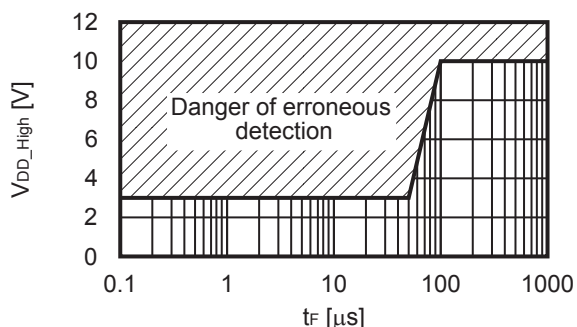


Figure 27

Remark Test conditions

Product name: S-19103C50

V_{SENSE} : $-V_{DET(S)} + 0.1$ V

V_{DD_High} : V_{DD} pin voltage before falling

V_{DD_Low} : V_{DD} pin voltage after falling (0.95 V)

ΔV_{DD} : $V_{DD_High} - V_{DD_Low}$

t_F : Falling time of V_{DD} from $V_{DD_High} - \Delta V_{DD} \times 10\%$ to $V_{DD_Low} + \Delta V_{DD} \times 10\%$

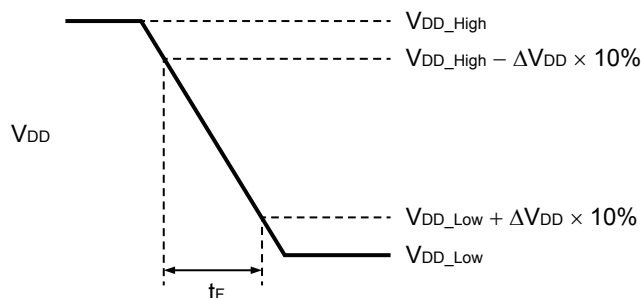


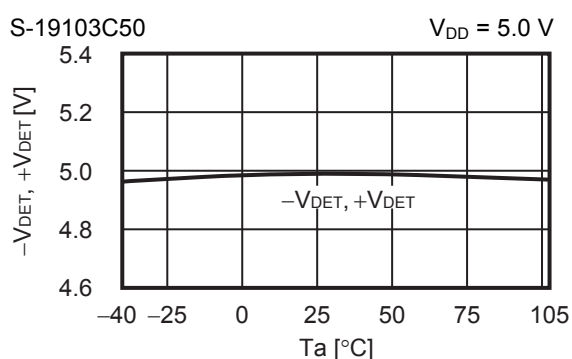
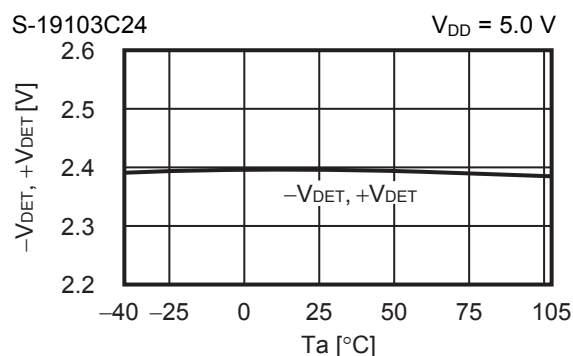
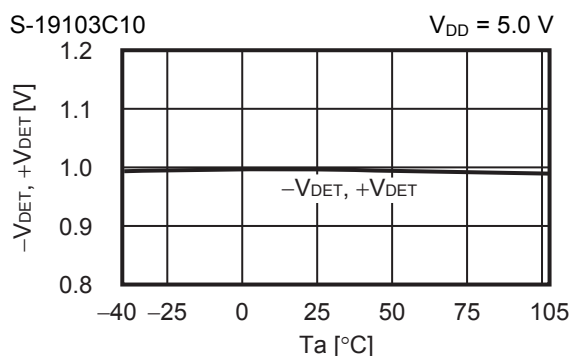
Figure 28

■ Precautions

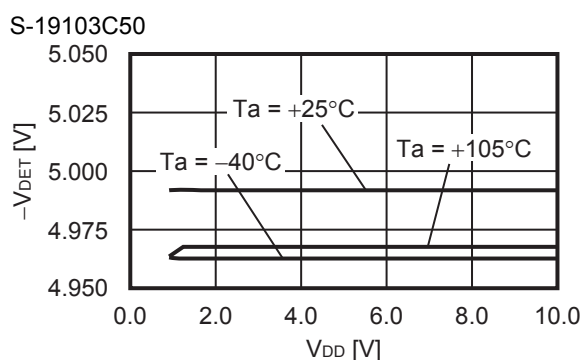
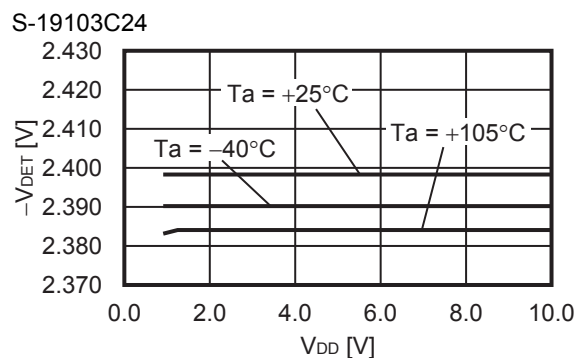
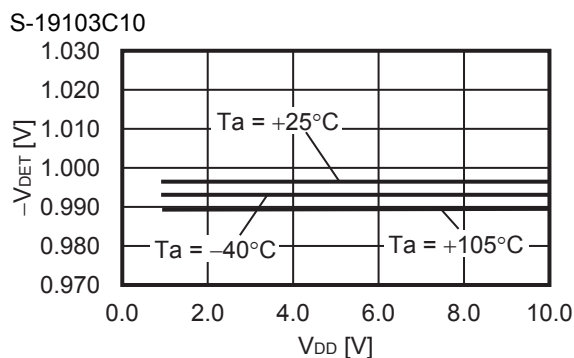
- Do not apply an electrostatic discharge to this IC that exceeds the performance ratings of the built-in electrostatic protection circuit.
- In CMOS output product of the S-19103/19109 Series, the feed-through current flows at the time of detection and release. If the VDD pin input impedance is high, malfunction may occur due to the voltage drop by the feed-through current when releasing.
- In CMOS output product, oscillation may occur if a pull-down resistor is connected and falling speed of the SENSE pin voltage (V_{SENSE}) is slow near the detection voltage when the VDD pin and the SENSE pin are shorted.
- When designing for mass production using an application circuit described herein, the product deviation and temperature characteristics of the external parts should be taken into consideration. SII Semiconductor Corporation shall not bear any responsibility for patent infringements related to products using the circuits described herein.
- SII Semiconductor Corporation claims no responsibility for any disputes arising out of or in connection with any infringement by products including this IC of patents owned by a third party.

■ Characteristics (Typical Data)

1. Detection voltage ($-V_{DET}$), Release voltage ($+V_{DET}$) vs. Temperature (T_a)

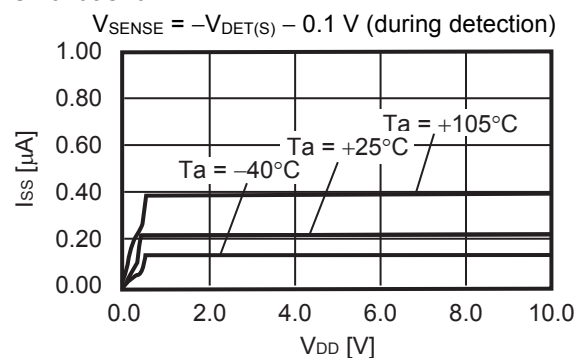


2. Detection voltage ($-V_{DET}$) vs. Power supply voltage (V_{DD})

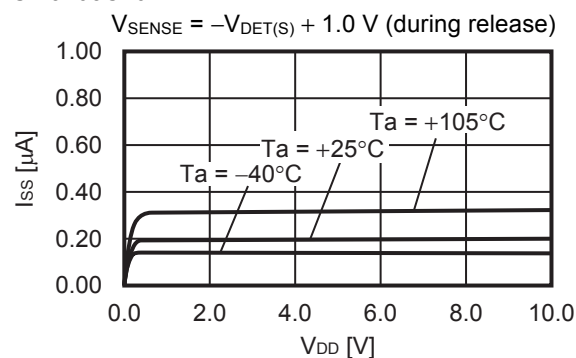


3. Current consumption (I_{SS}) vs. Power supply voltage (V_{DD})

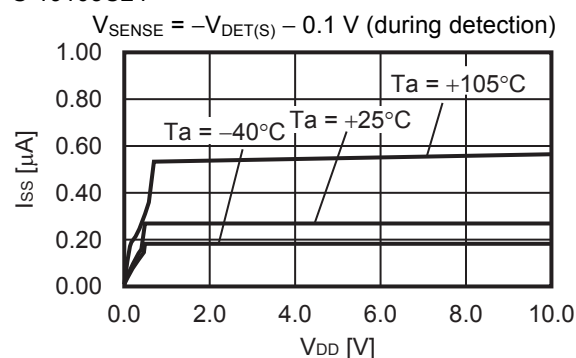
S-19103C10



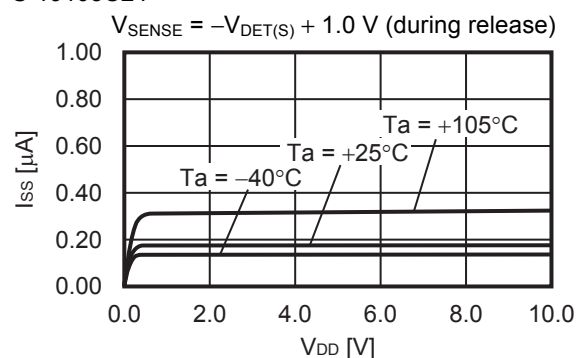
S-19103C10



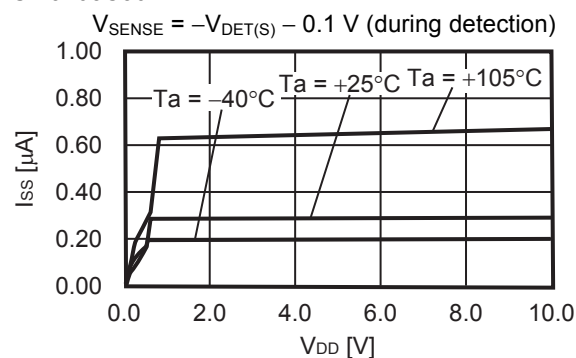
S-19103C24



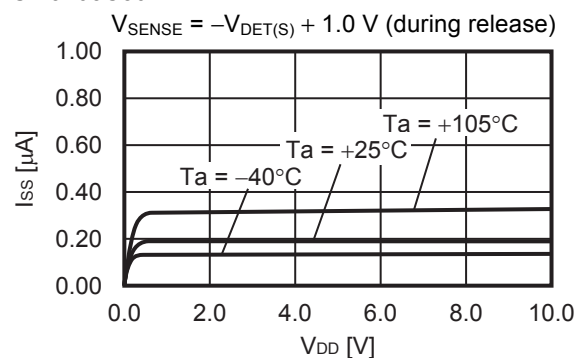
S-19103C24



S-19103C50

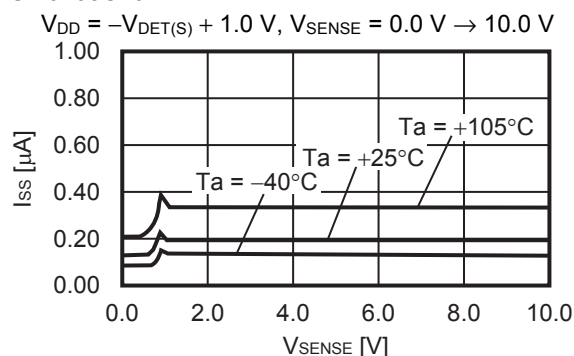


S-19103C50

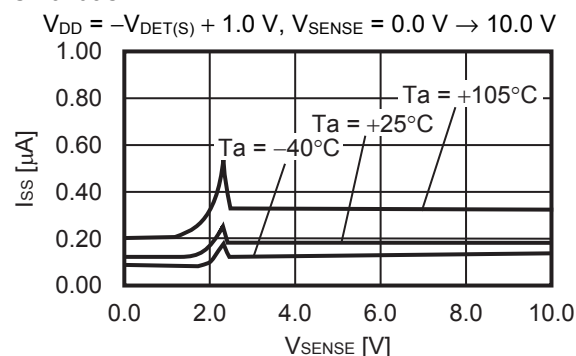


4. Current consumption (I_{SS}) vs. SENSE pin input voltage (V_{SENSE})

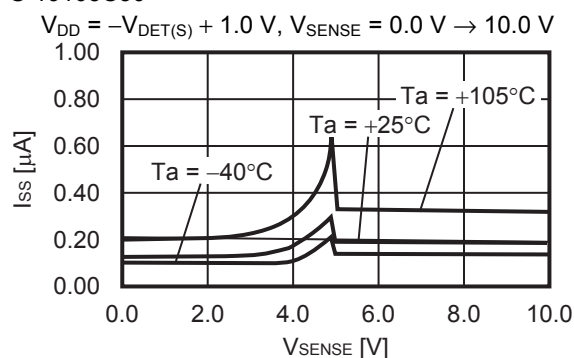
S-19103C10



S-19103C24

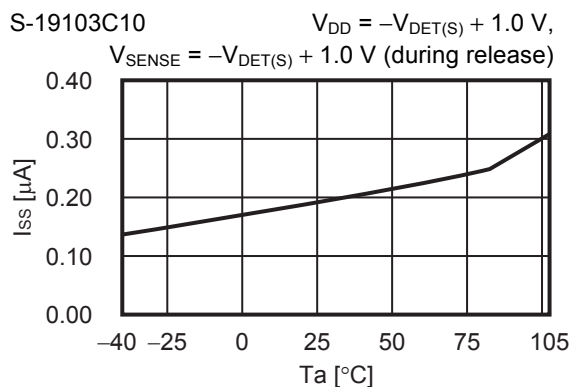


S-19103C50

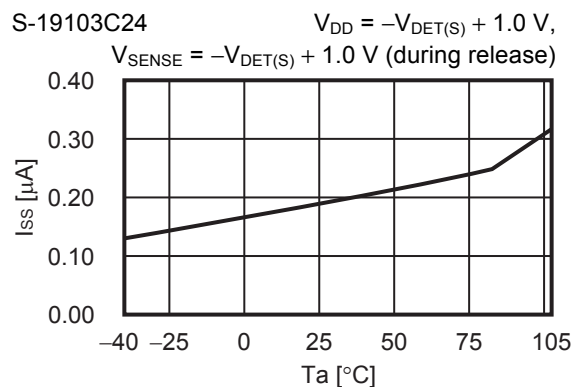


5. Current consumption (I_{SS}) vs. Temperature (T_a)

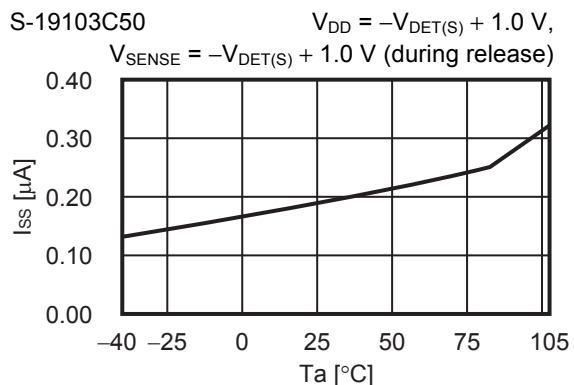
S-19103C10



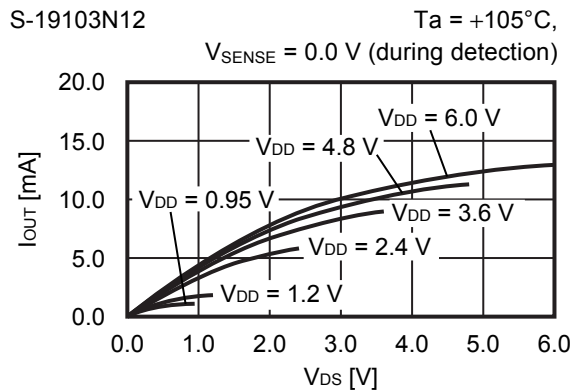
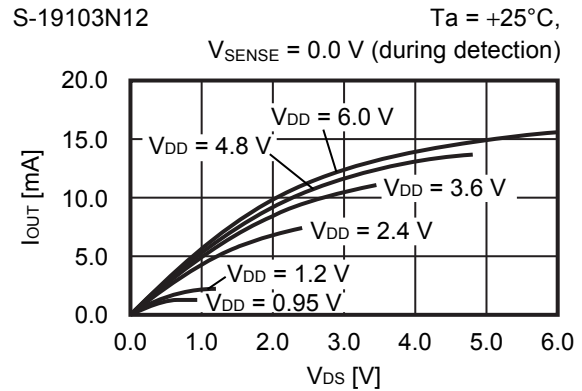
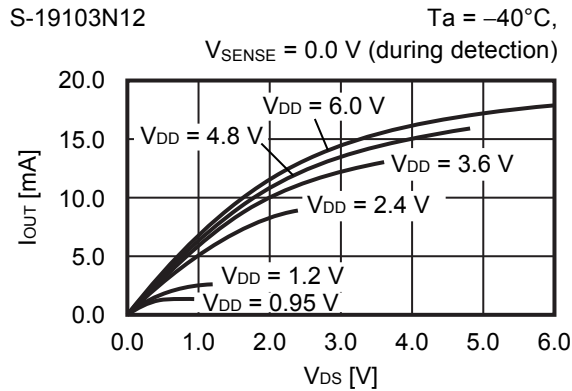
S-19103C24



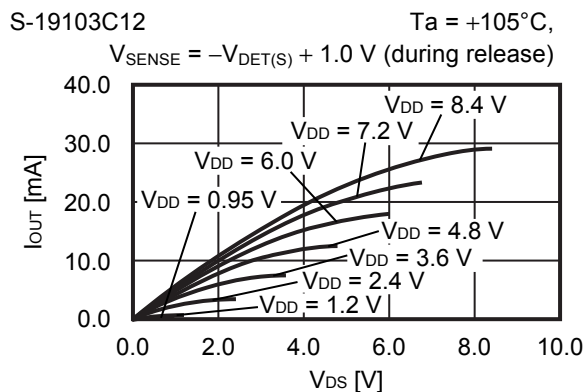
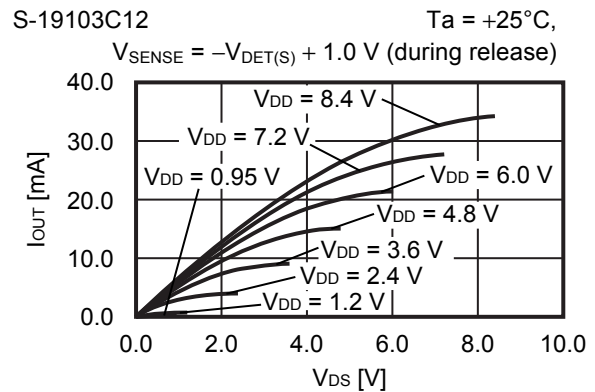
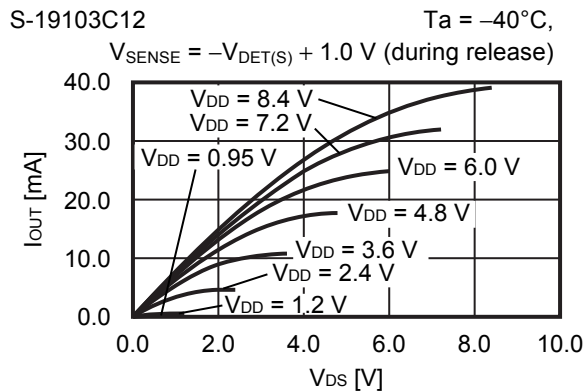
S-19103C50



6. Nch transistor output current (I_{OUT}) – V_{DS}

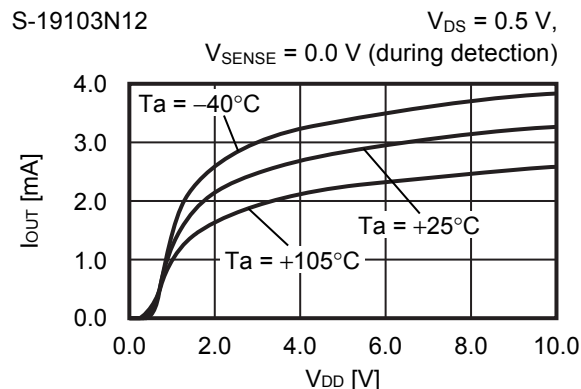


7. Pch transistor output current (I_{OUT}) – V_{DS}

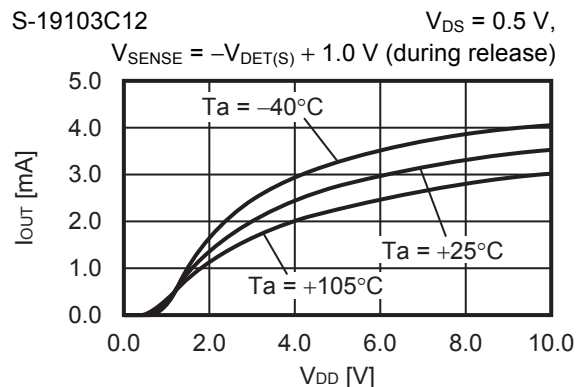


Remark V_{DS} : Drain-to-source voltage of the output transistor

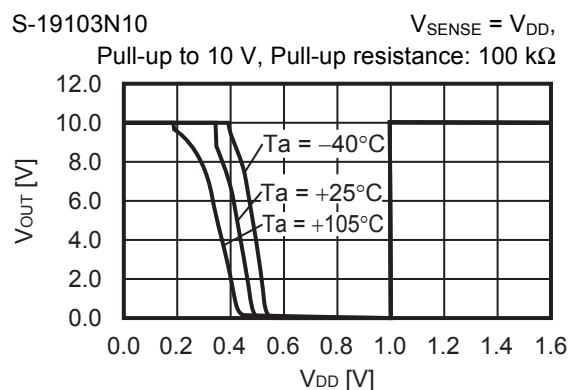
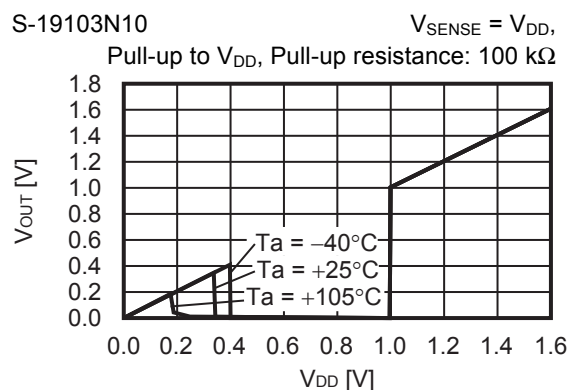
8. Nch transistor output current (I_{OUT}) vs. Power supply voltage (V_{DD})



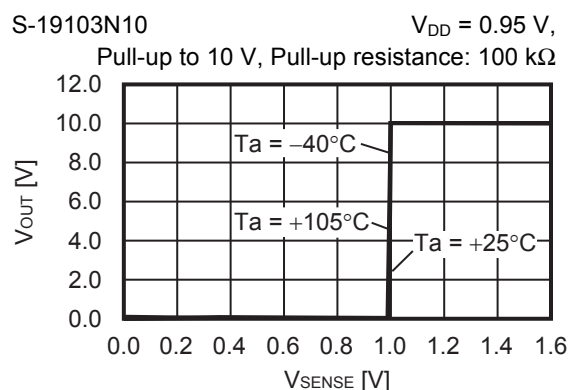
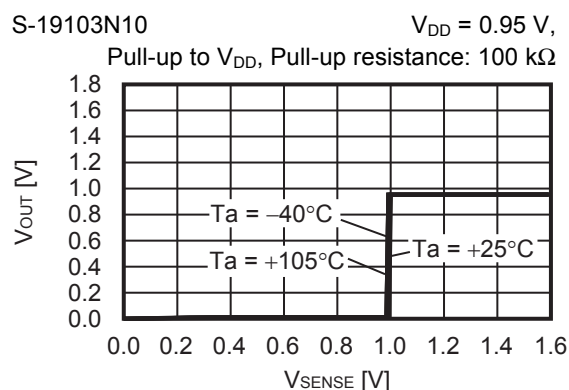
9. Pch transistor output current (I_{OUT}) vs. Power supply voltage (V_{DD})



10. Minimum operation voltage (V_{OUT}) vs. Power supply voltage (V_{DD})

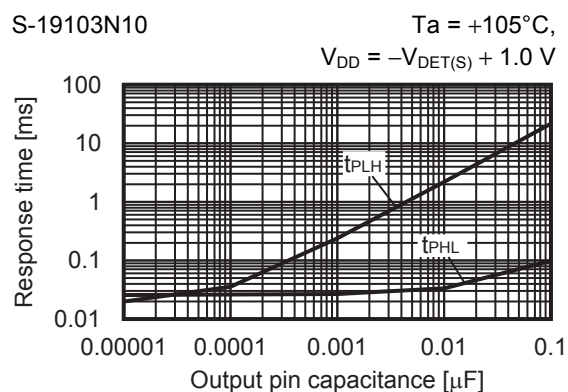
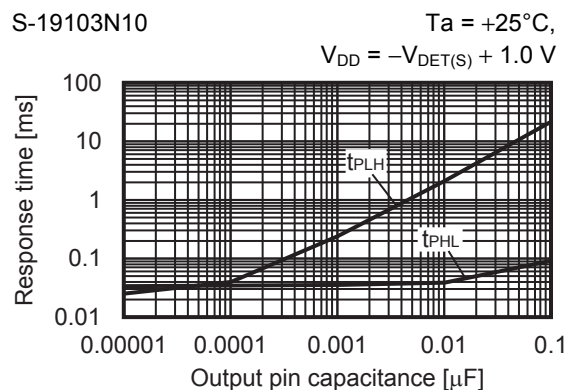
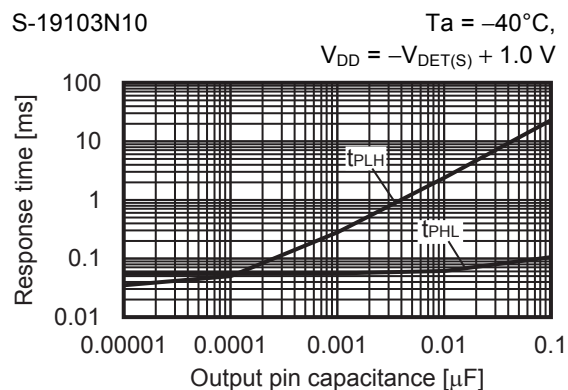
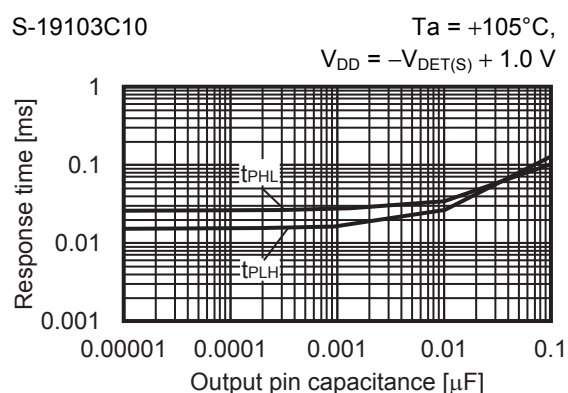
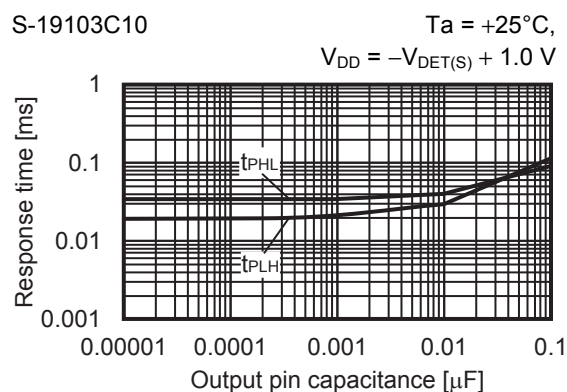
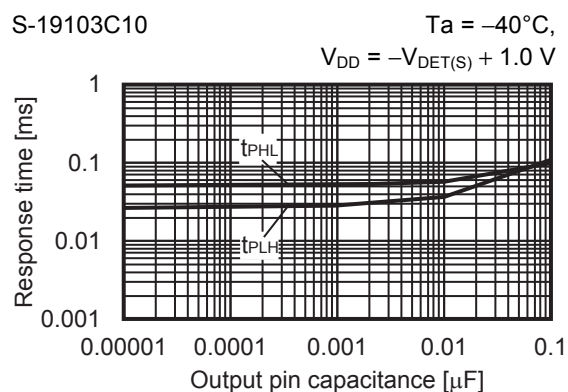


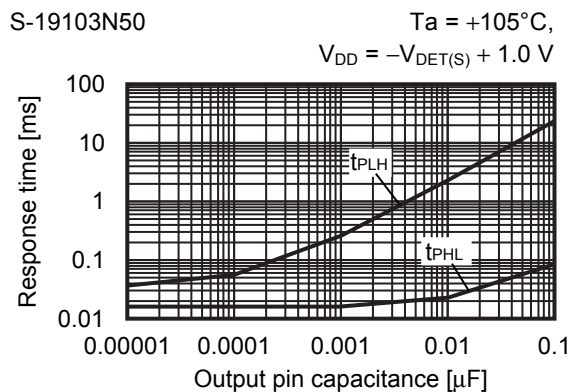
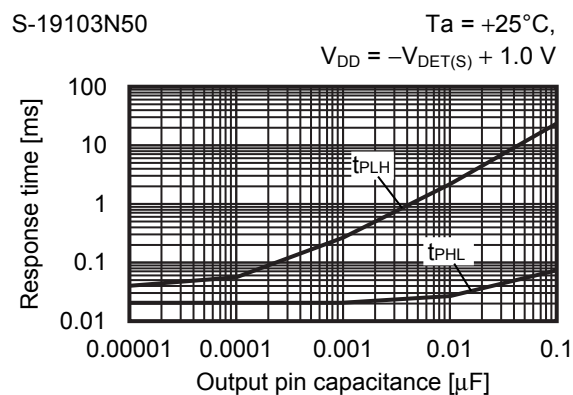
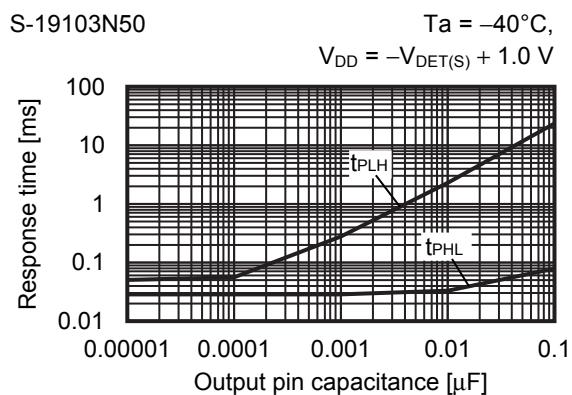
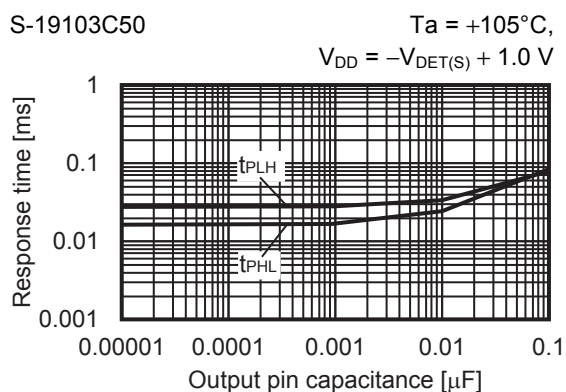
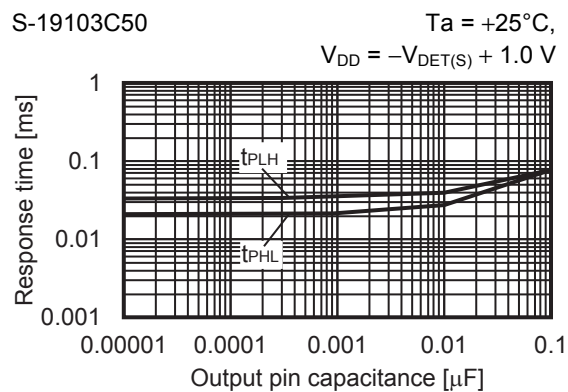
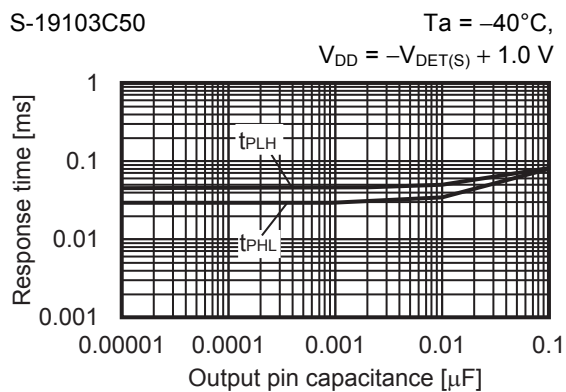
11. Minimum operation voltage (V_{OUT}) vs. SENSE pin input voltage (V_{SENSE})



Remark V_{DS} : Drain-to-source voltage of the output transistor

12. Dynamic response vs. Output pin capacitance (C_{OUT})





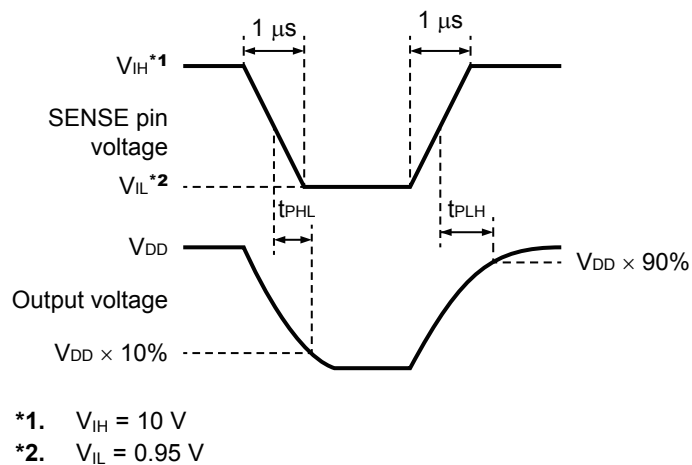


Figure 29 Test Condition of Response Time

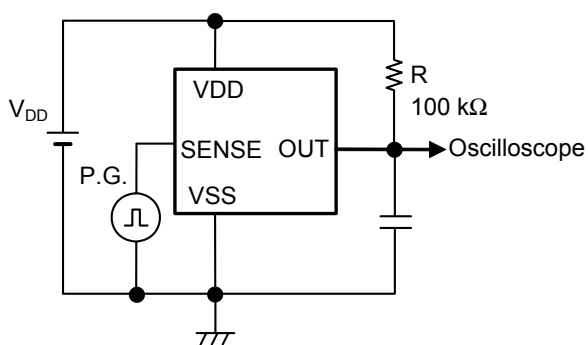


Figure 30 Test Circuit of Response Time
(Nch open-drain output product)

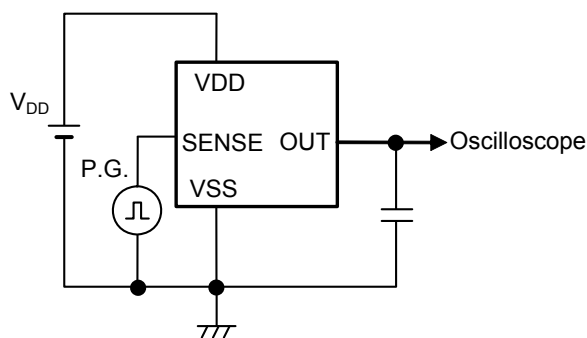


Figure 31 Test Circuit of Response Time
(CMOS output product)

Caution The above connection diagram and constant will not guarantee successful operation. Perform thorough evaluation using the actual application to set the constant.

■ Thermal Characteristics

1. SOT-23-5

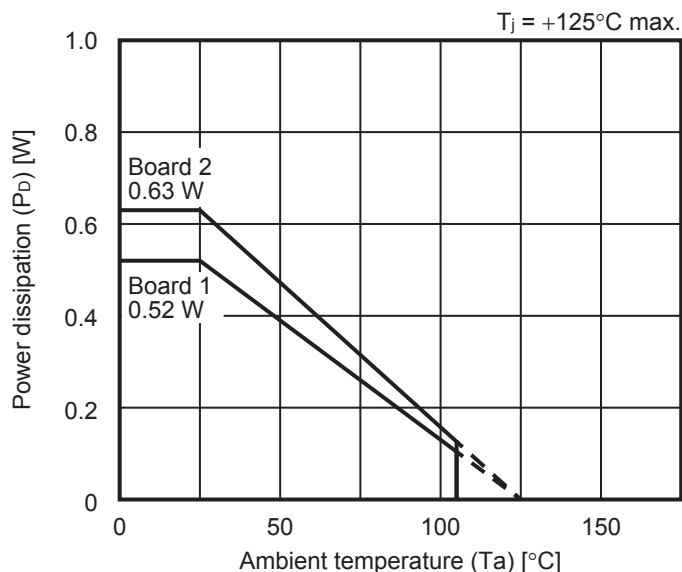


Figure 32 Power Dissipation of Package (When Mounted on Board)

1.1 Board 1^{*1}

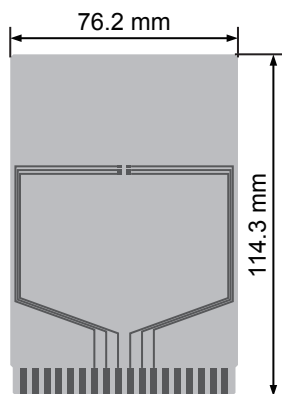


Figure 33

Table 13

Item		Specification
Thermal resistance value (θ_{ja})		192°C/W
Size		114.3 mm × 76.2 mm × t1.6 mm
Material		FR-4
Number of copper foil layer		2
Copper foil layer	1	Land pattern and wiring for testing: t0.070 mm
	2	—
	3	—
	4	74.2 mm × 74.2 mm × t0.070 mm
Thermal via		—

1.2 Board 2^{*1}

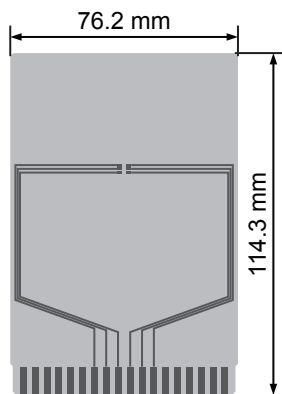
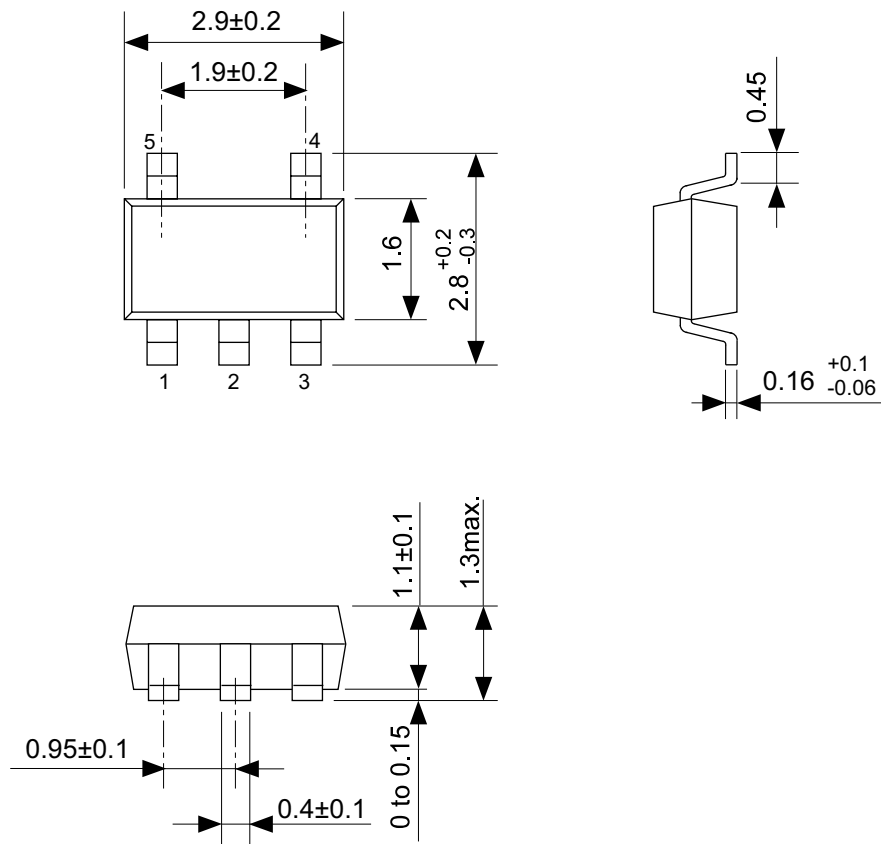


Figure 34

Table 14

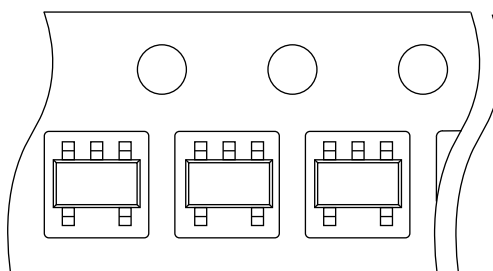
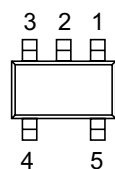
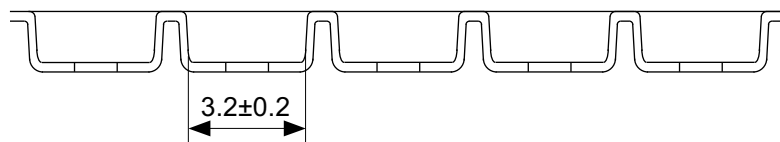
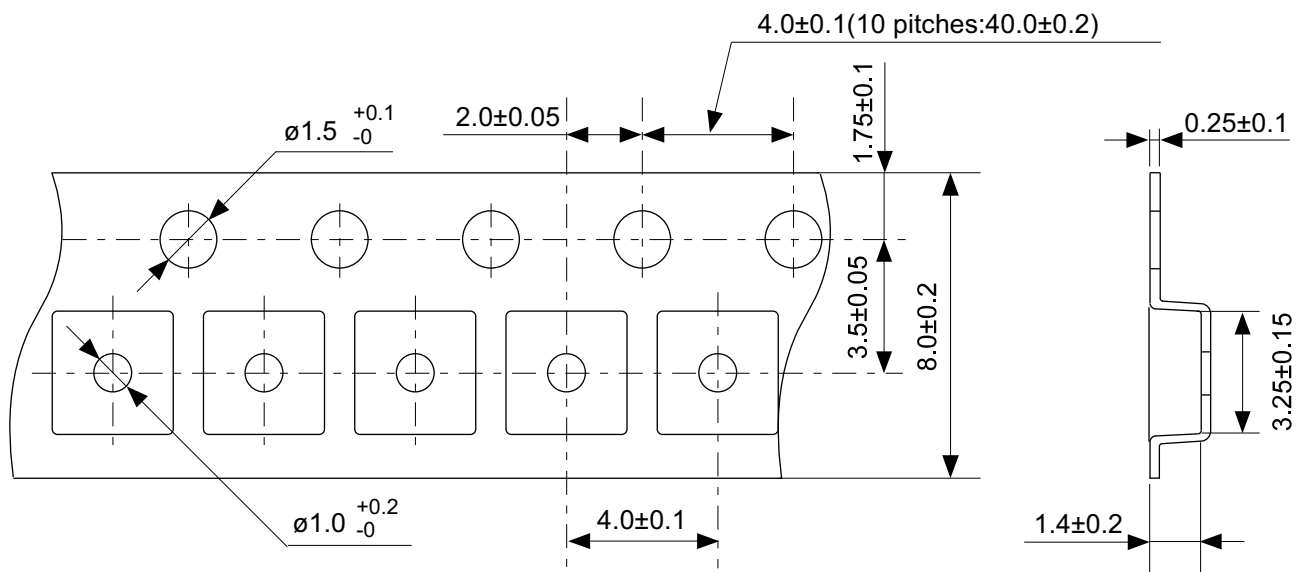
Item		Specification
Thermal resistance value (θ_{ja})		160°C/W
Size		114.3 mm × 76.2 mm × t1.6 mm
Material		FR-4
Number of copper foil layer		4
Copper foil layer	1	Land pattern and wiring for testing: t0.070 mm
	2	74.2 mm × 74.2 mm × t0.035 mm
	3	74.2 mm × 74.2 mm × t0.035 mm
	4	74.2 mm × 74.2 mm × t0.070 mm
Thermal via		—

*1. The board is same in SOT-23-3, SOT-23-5 and SOT-23-6.



No. MP005-A-P-SD-1.3

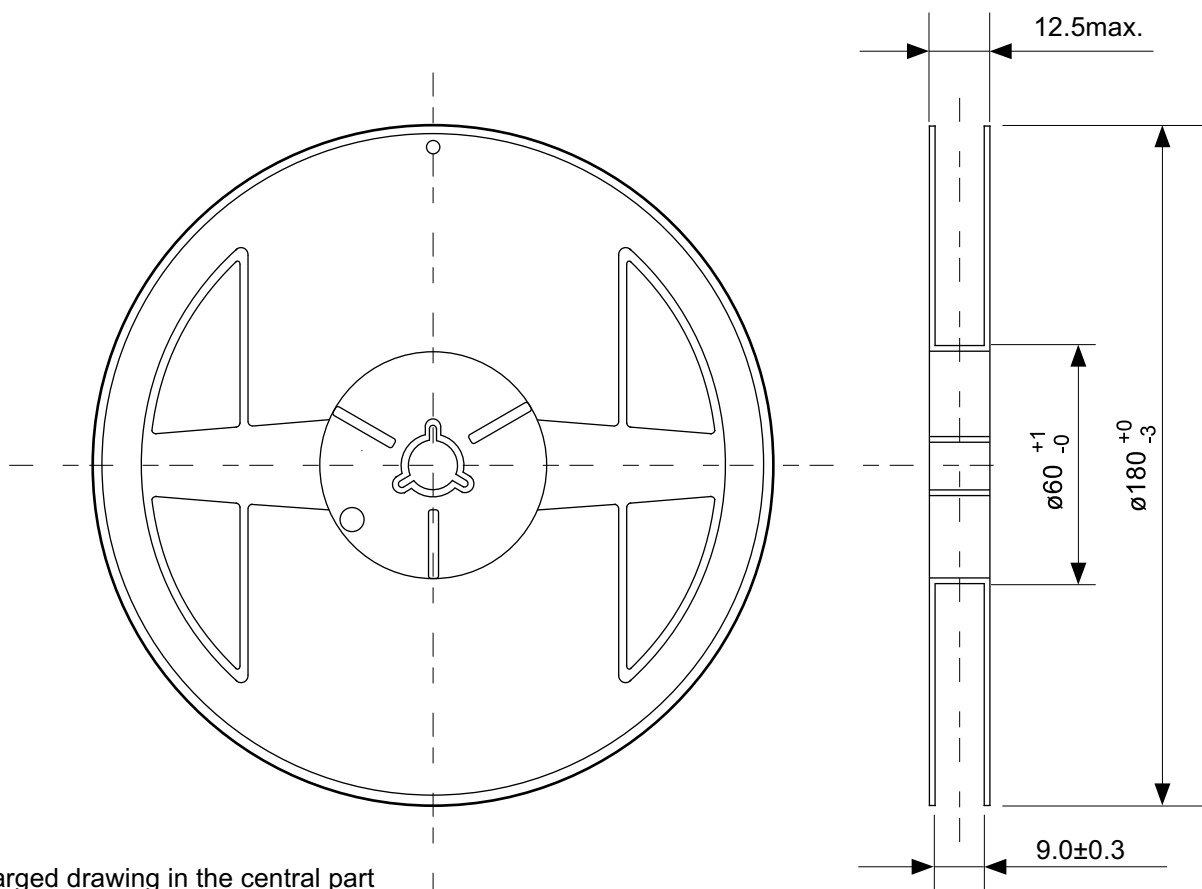
TITLE	SOT235-A-PKG Dimensions
No.	MP005-A-P-SD-1.3
ANGLE	
UNIT	mm
SII Semiconductor Corporation	



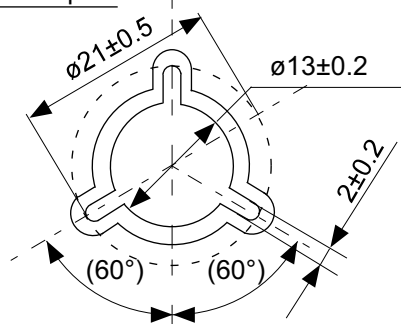
Feed direction →

No. MP005-A-C-SD-2.1

TITLE	SOT235-A-Carrier Tape
No.	MP005-A-C-SD-2.1
ANGLE	
UNIT	mm
SII Semiconductor Corporation	



Enlarged drawing in the central part



No. MP005-A-R-SD-1.1

TITLE	SOT235-A-Reel		
No.	MP005-A-R-SD-1.1		
ANGLE		QTY.	3,000
UNIT	mm		
SII Semiconductor Corporation			

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